

# Semiconductor Devices II

Part 2

Chapter 2: Defects in 2D materials

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**EPFL**

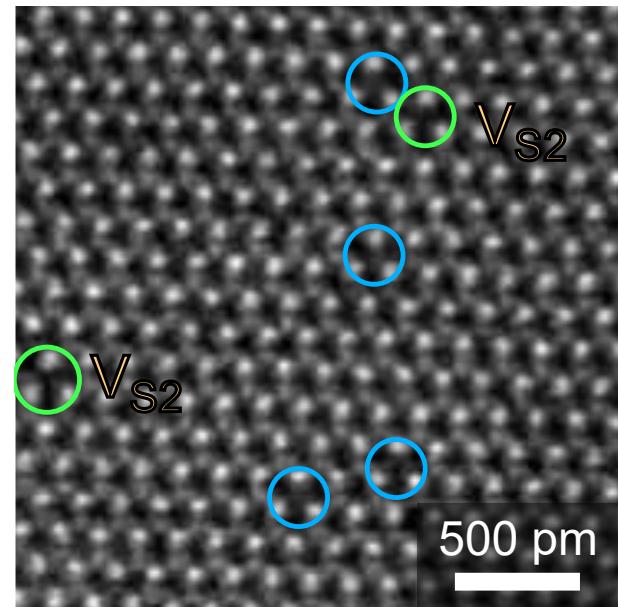
# [Outline] Chapter 2: Defects in 2D materials

- Overview of defects in 2D materials
- Point defects
- How to mitigate (some) defects
- Positive applications of defects

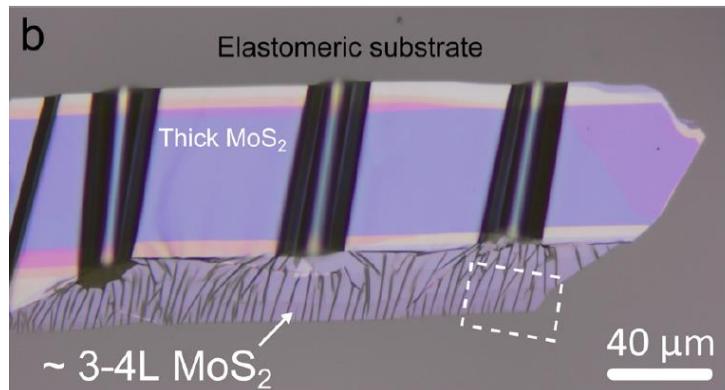
# Most common defect types in 2D

- Point defects
  - vacancies
  - substitutions
  - dopants
- Line defects
  - grain boundaries
  - lateral heterostructures
  - vacancy lines
- Two-dimensional defects
  - wrinkles
  - ripples

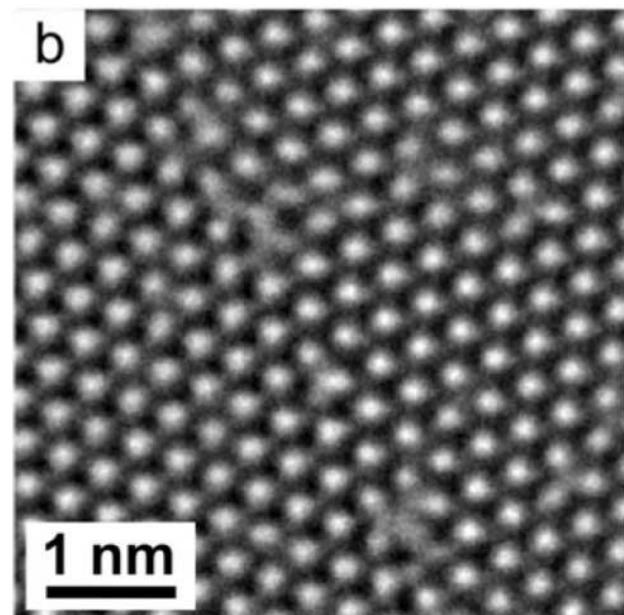
*Crystals are like people, it is the defects in them which tend to make them interesting!*  
- Sir Colin Humphreys,  
CBE FRS FREng FIMMM FInstP



Dumcenco et al. 2D Mater. (2015)



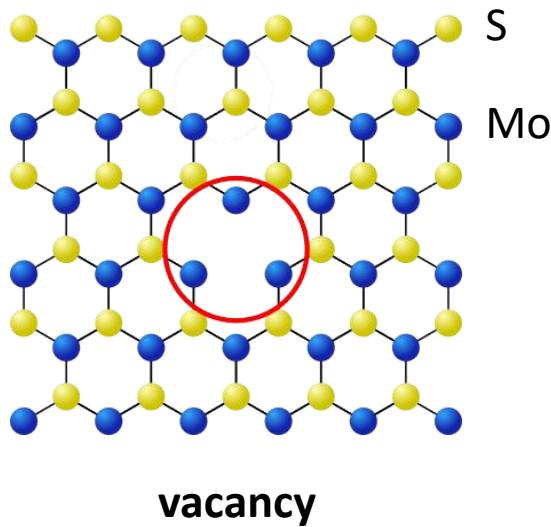
Castellanos-Gomez et al. Nano Letters (2013)



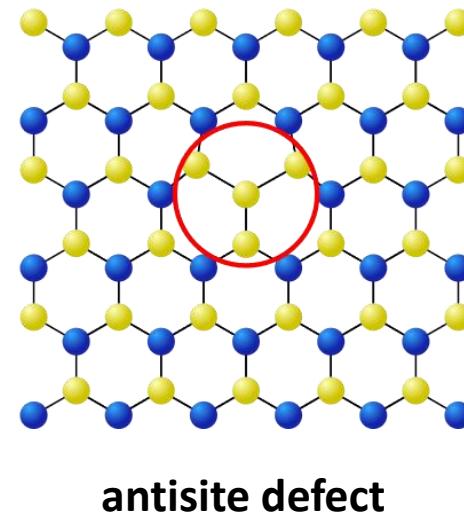
ACS Nano (2015) Lehtinen

# Most common defects: point defects

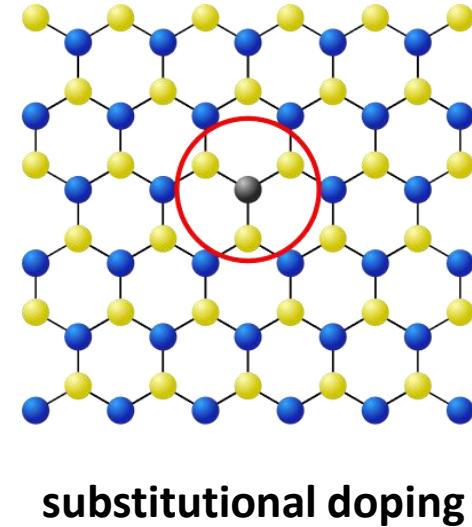
Missing atom



Native atom in the wrong place



Foreign atom



Nomenclature:

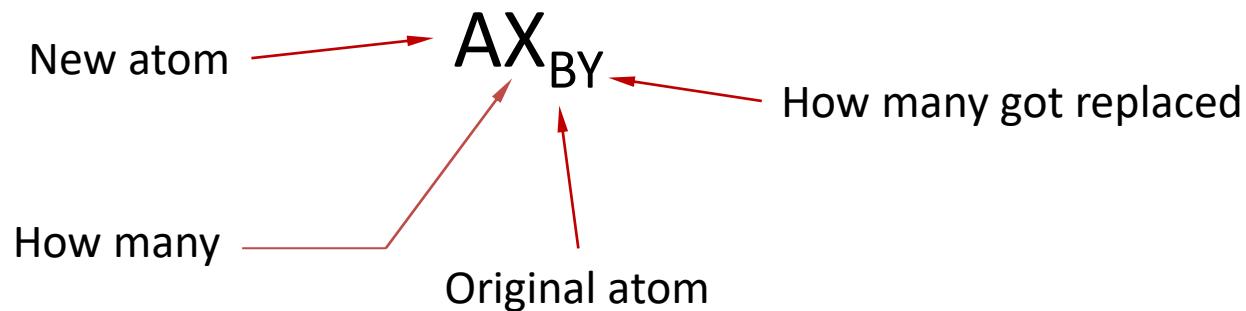
AX<sub>BY</sub>

New atom

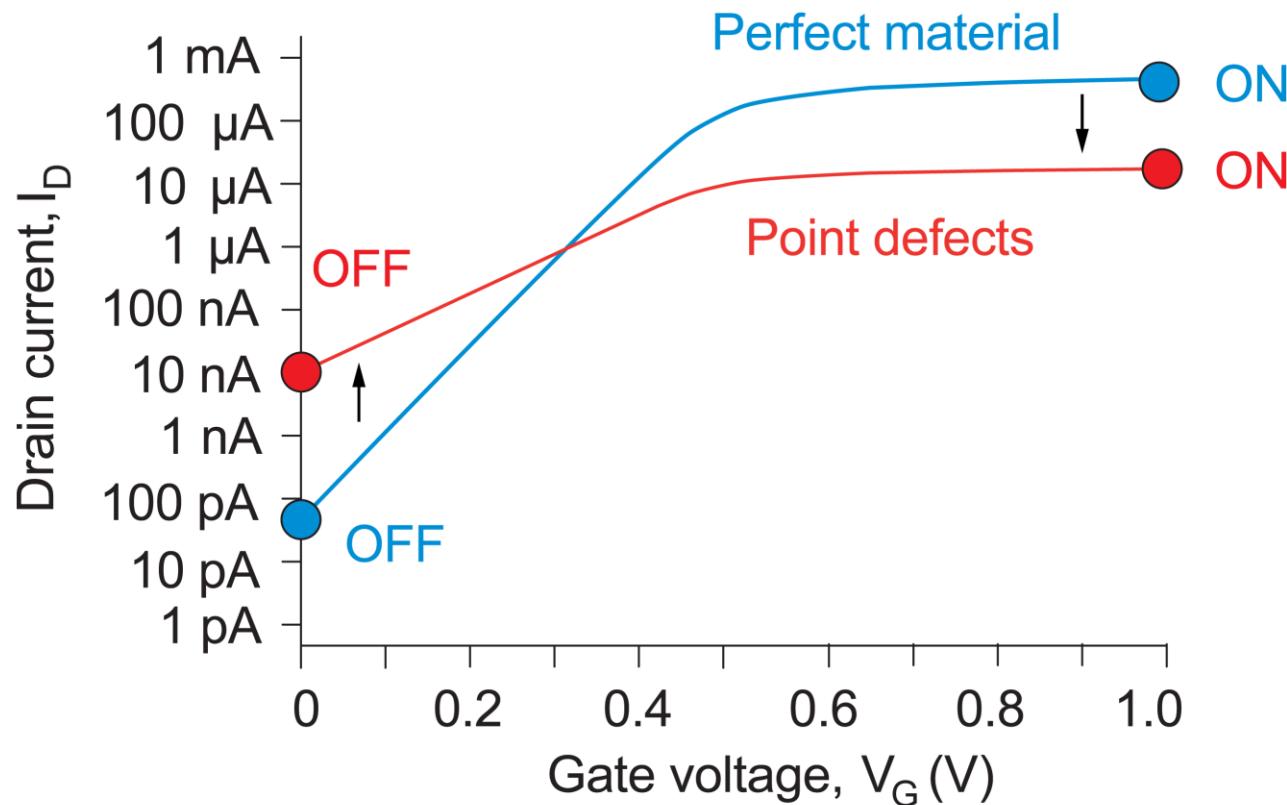
How many got replaced

How many

Original atom



# Influence of point defects on FET characteristics



ON current: decreases

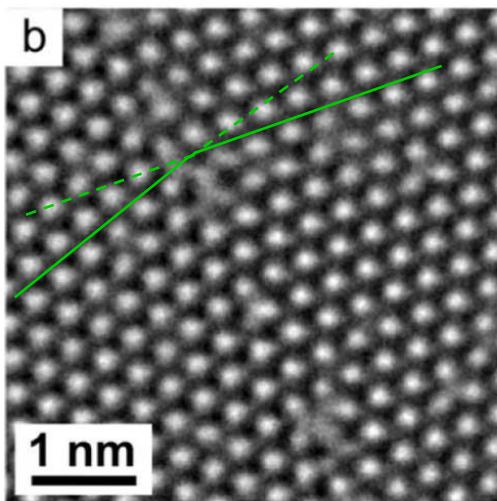
OFF current: increases

$I_{ON}/I_{OFF}$ : decreases

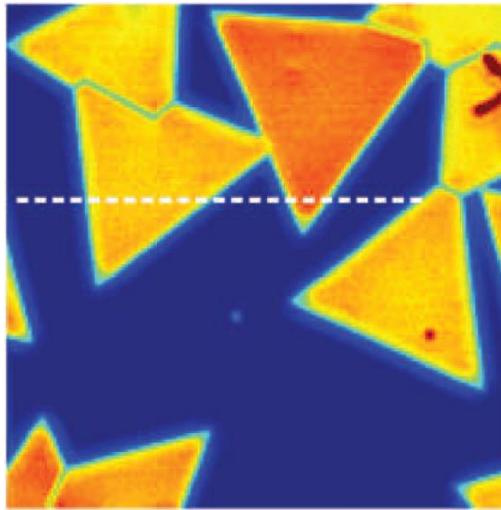
Subthreshold swing: increases

# Most common defects: line defects

Grain boundaries

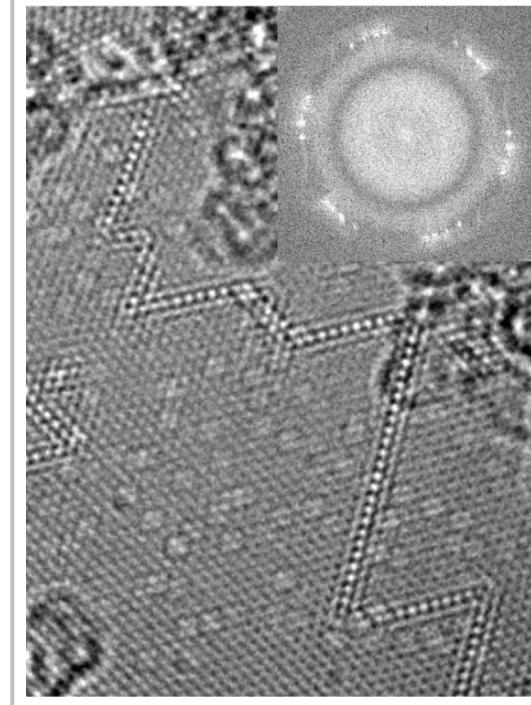
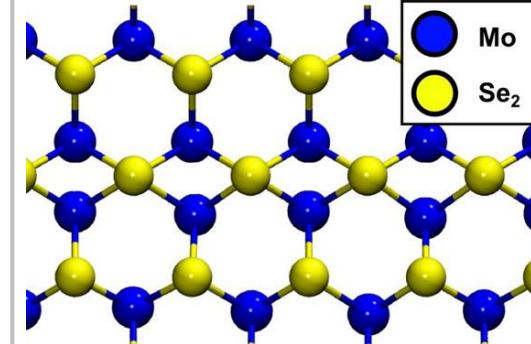


Lehtinen et al. ACS Nano (2015)

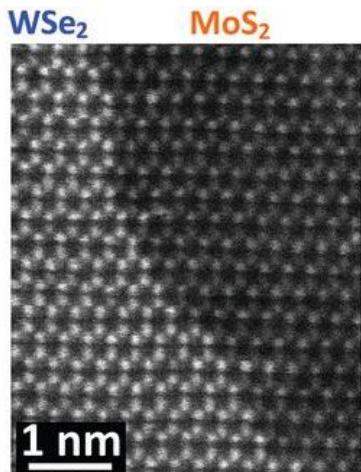


Yin et al. Science (2014)

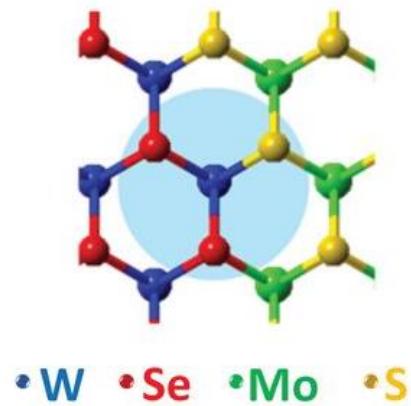
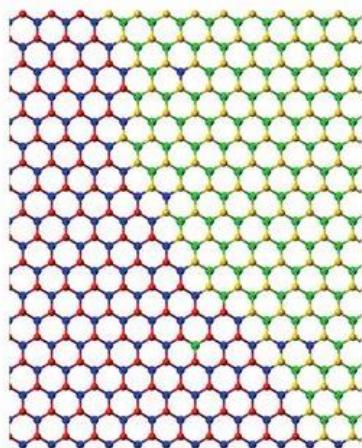
Vacancy lines



Lateral heterostructures



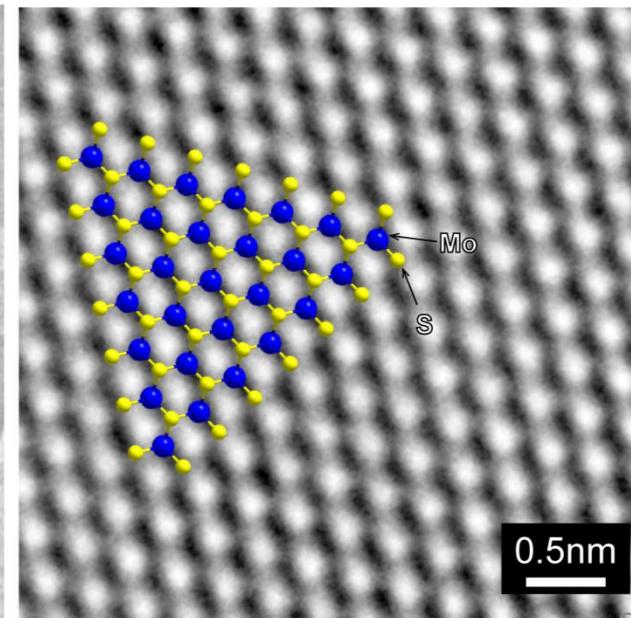
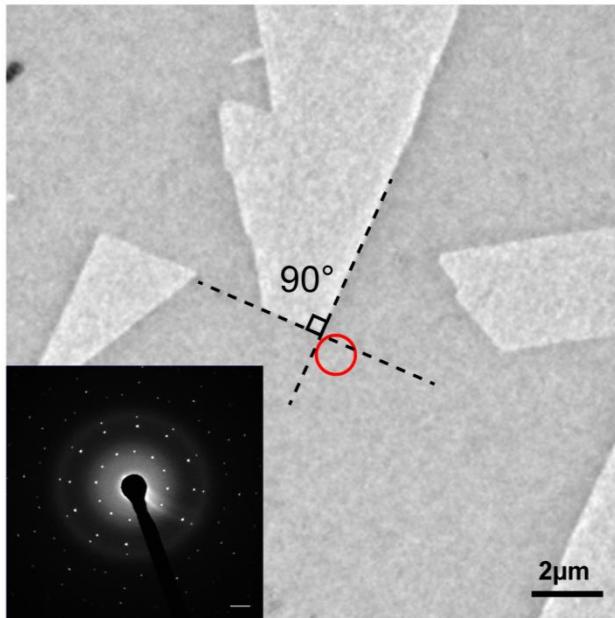
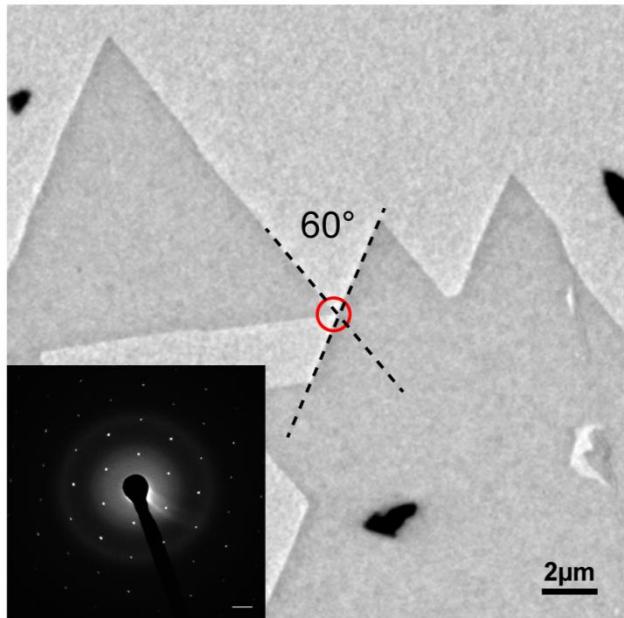
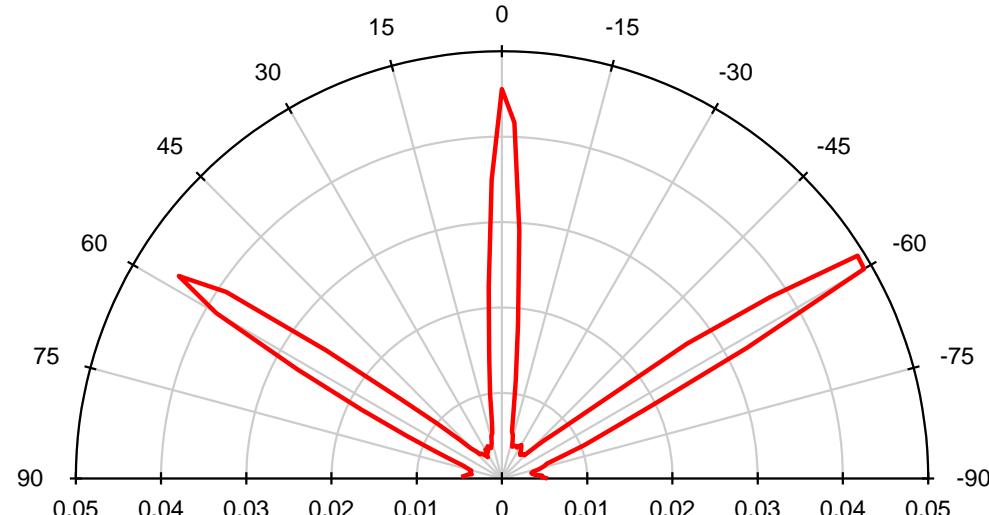
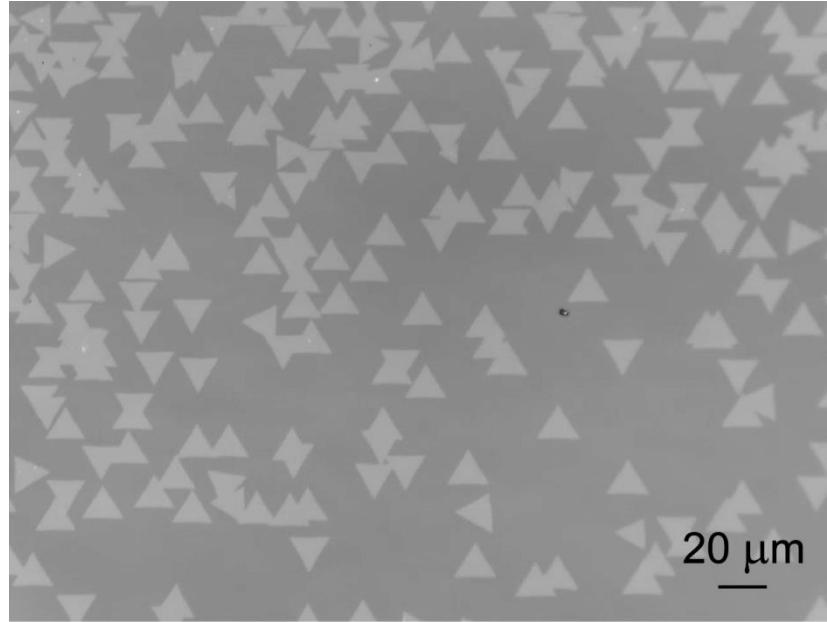
Li et al, Science (2015)



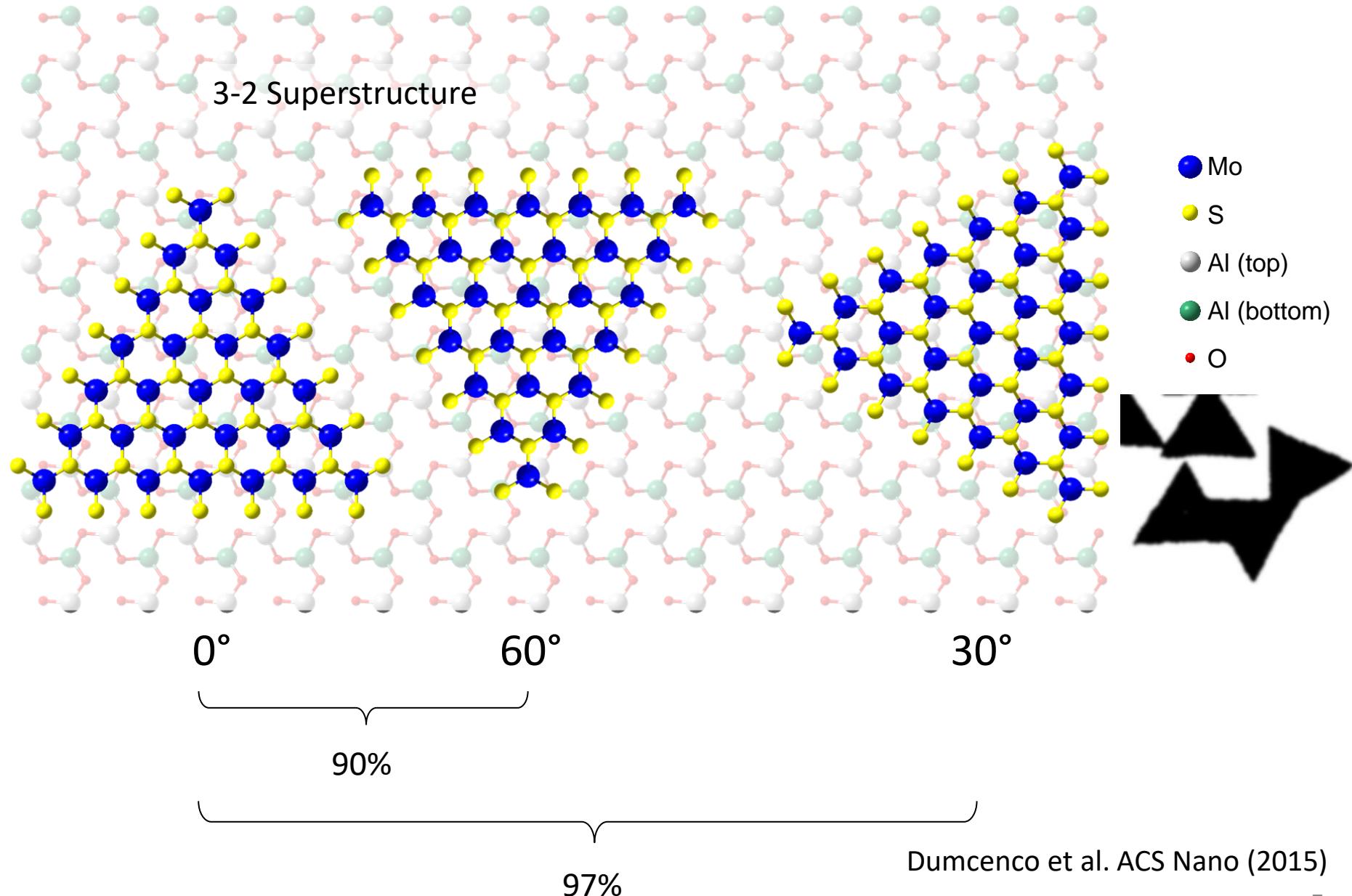
• W • Se • Mo • S

Lehtinen et al. ACS Nano (2015)

# Can we avoid grain boundaries?

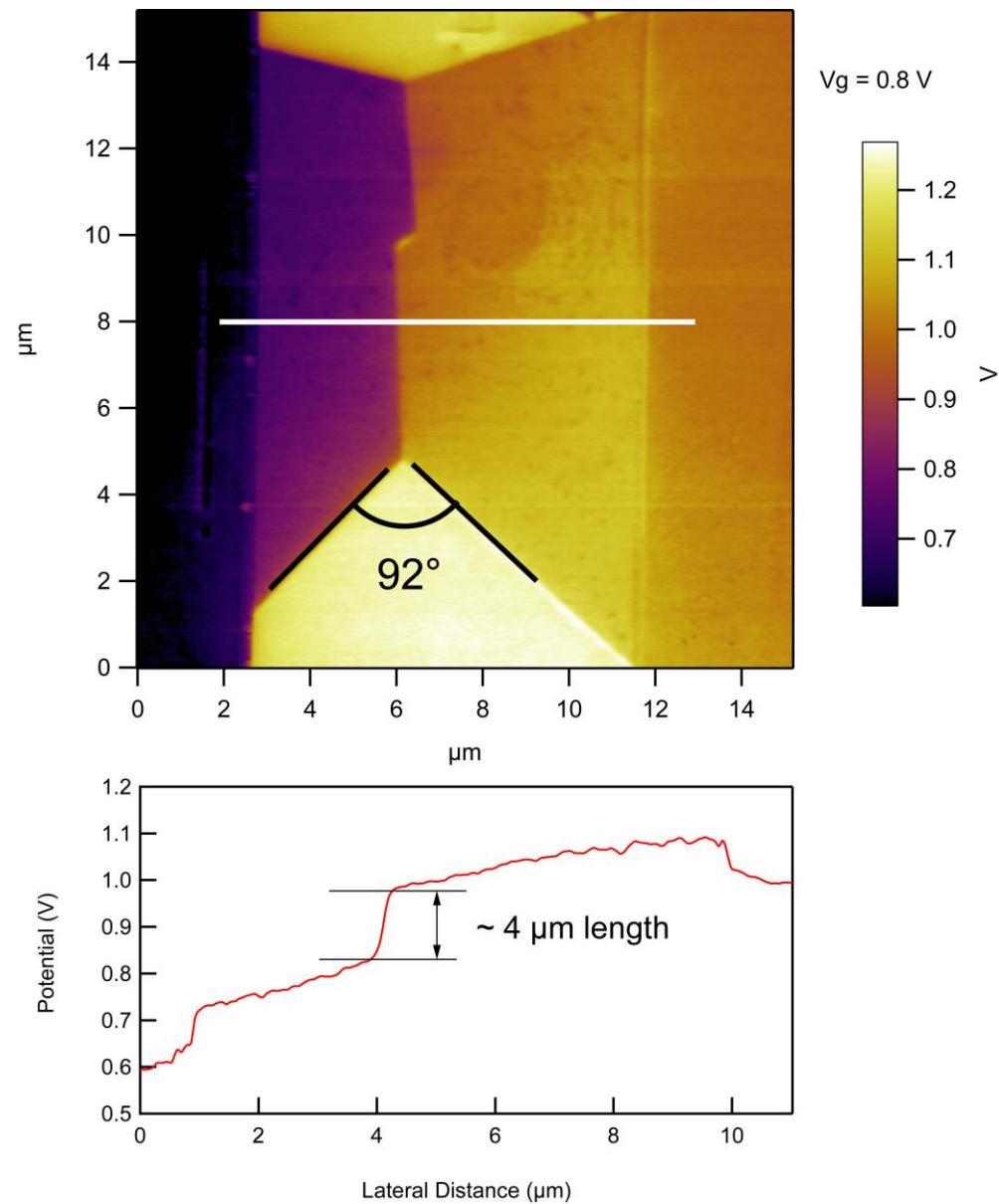
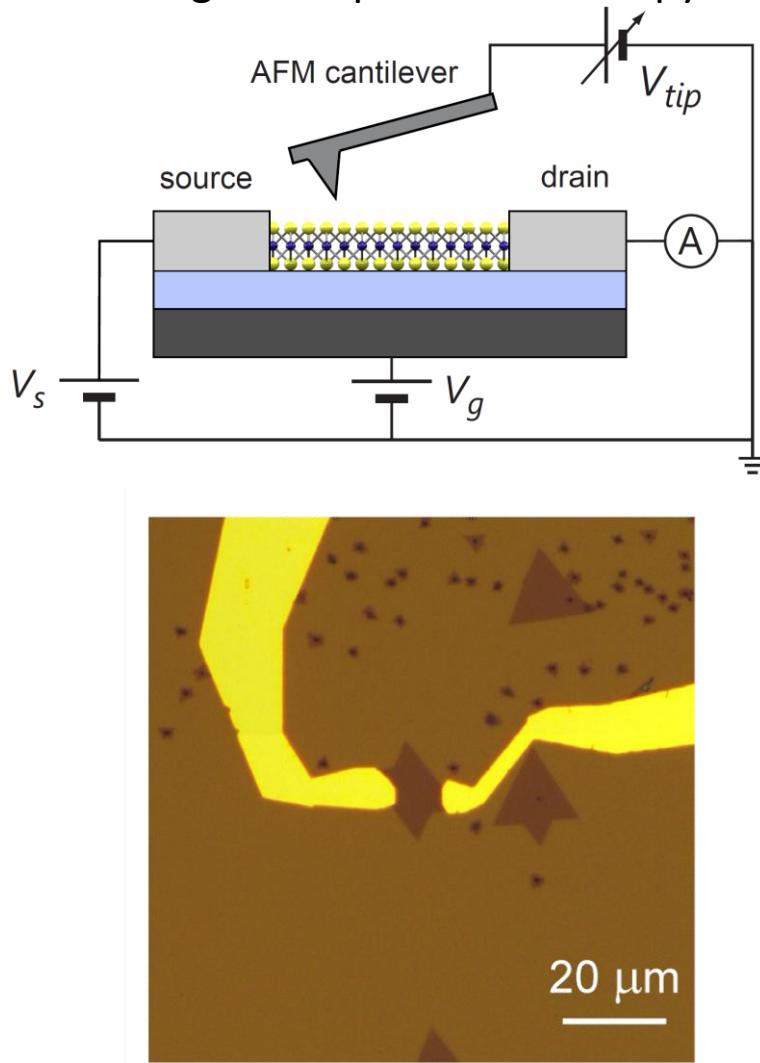


# Epitaxial CVD MoS<sub>2</sub>: domain orientations



# Conductivity and grain boundaries

## Scanning Kelvin probe microscopy



# Conductivity and grain boundaries



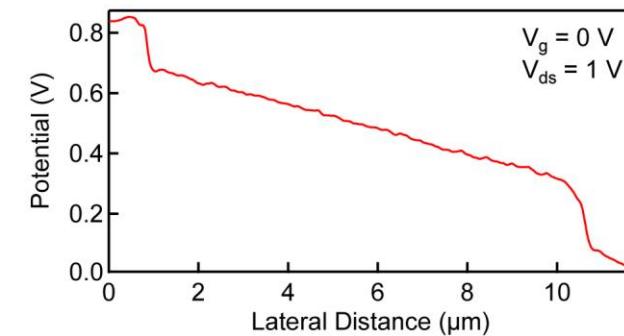
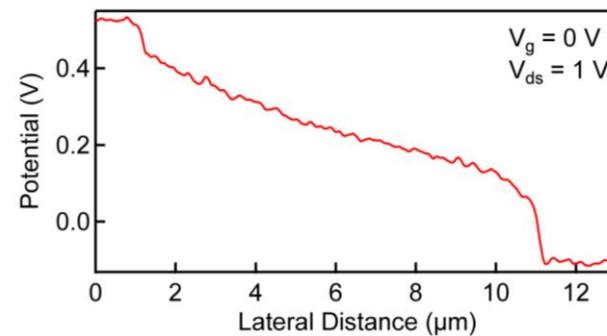
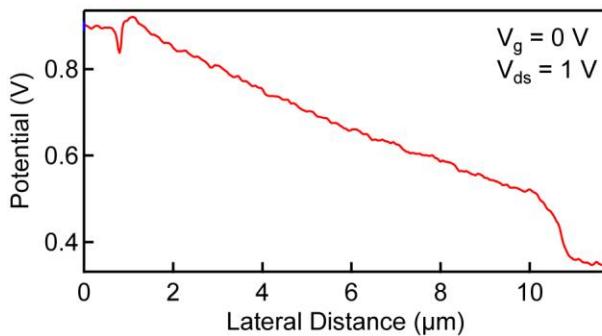
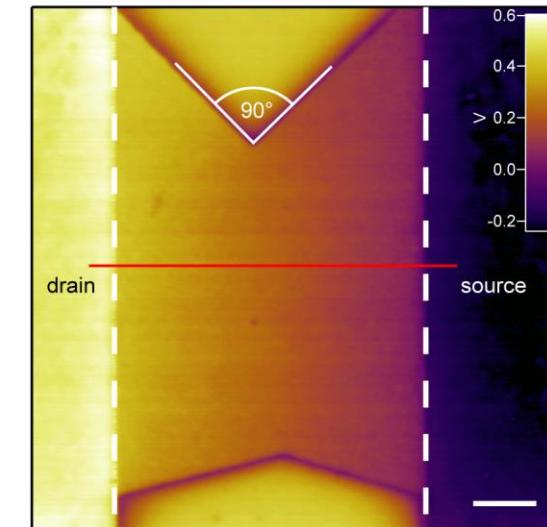
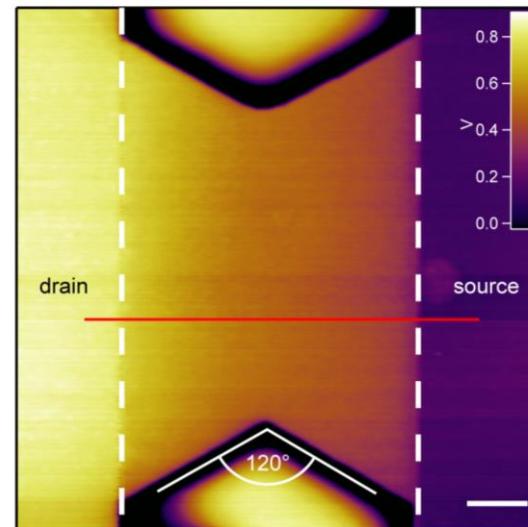
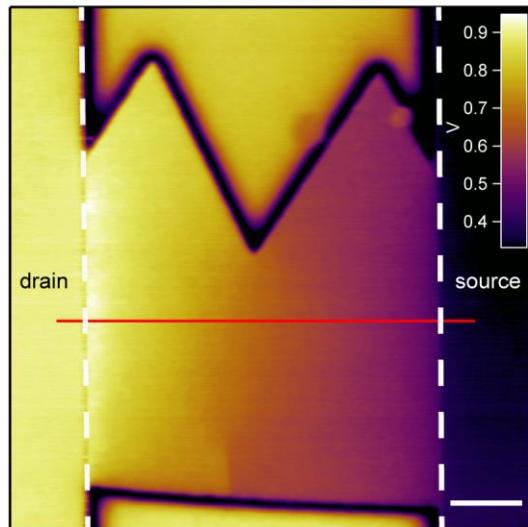
$$\theta_{\text{rel}} = 0^\circ$$



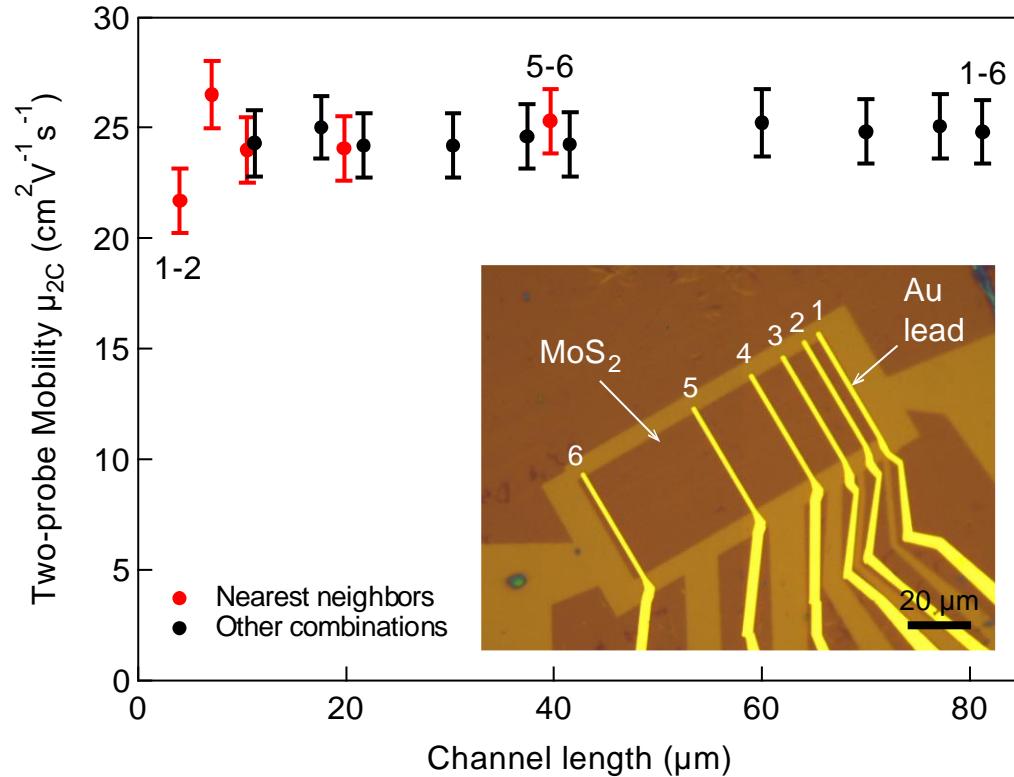
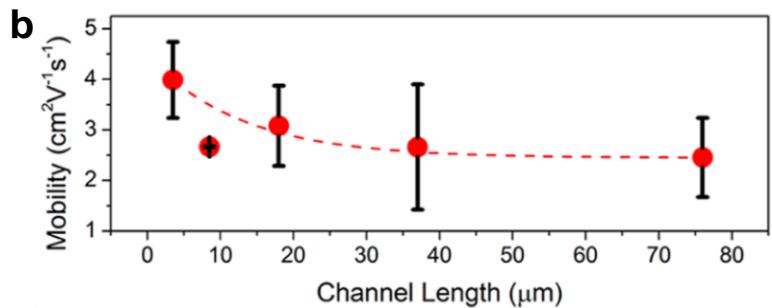
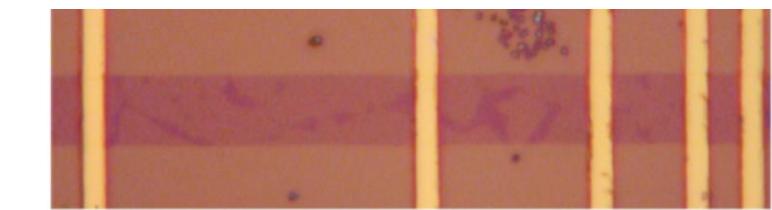
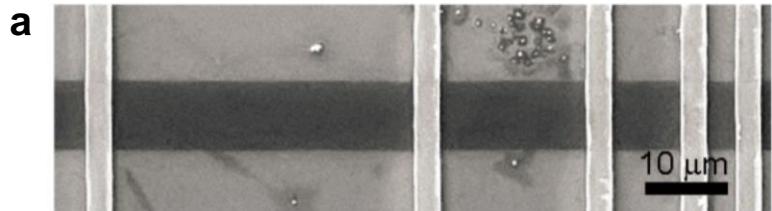
$$\theta_{\text{rel}} = 60^\circ$$



$$\theta_{\text{rel}} = 30^\circ$$



# Conductivity and grain boundaries

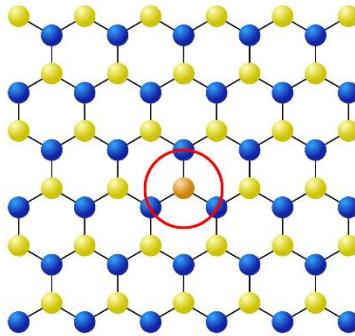
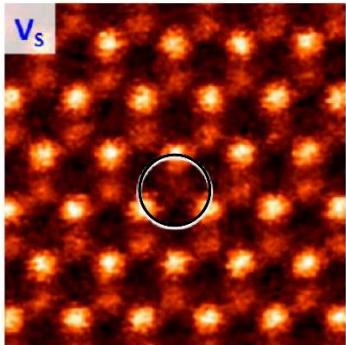


Najmaei, Ajayan et al. ACS Nano 2014

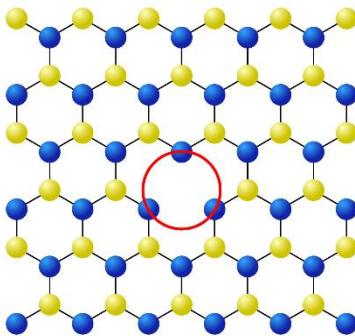
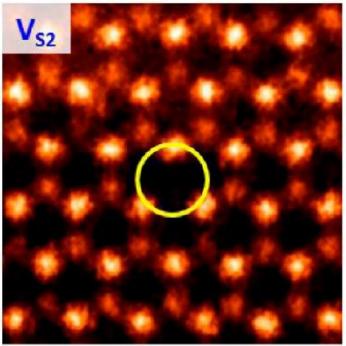
Dumcenco...Kis; ACS Nano (2015)

# Most common point defects in $\text{MoS}_2$

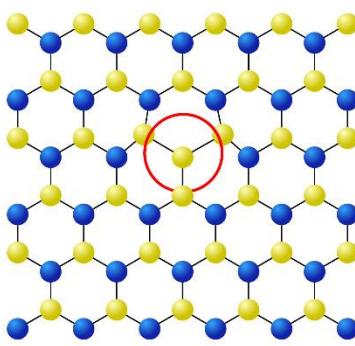
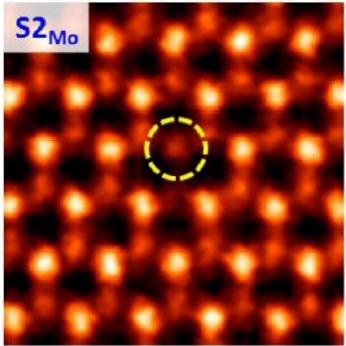
$\text{V}_\text{S}$



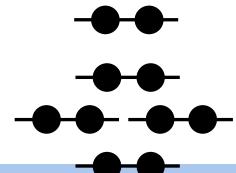
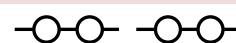
$\text{V}_{\text{S}2}$



$\text{S2}_{\text{Mo}}$



Conduction band



Valence band

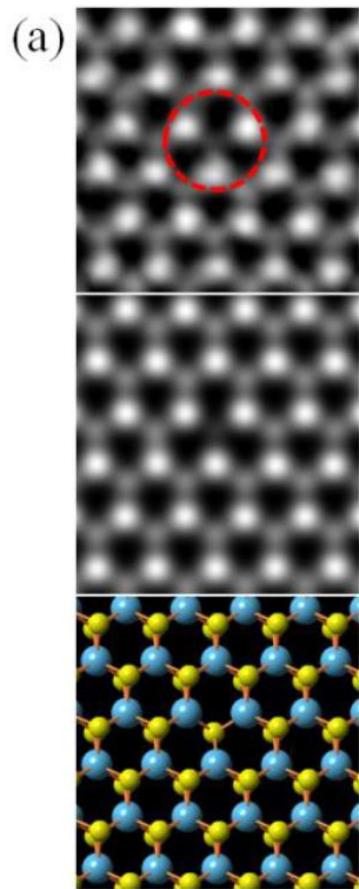
$\text{V}_\text{S}$

$\text{V}_{\text{S}2}$

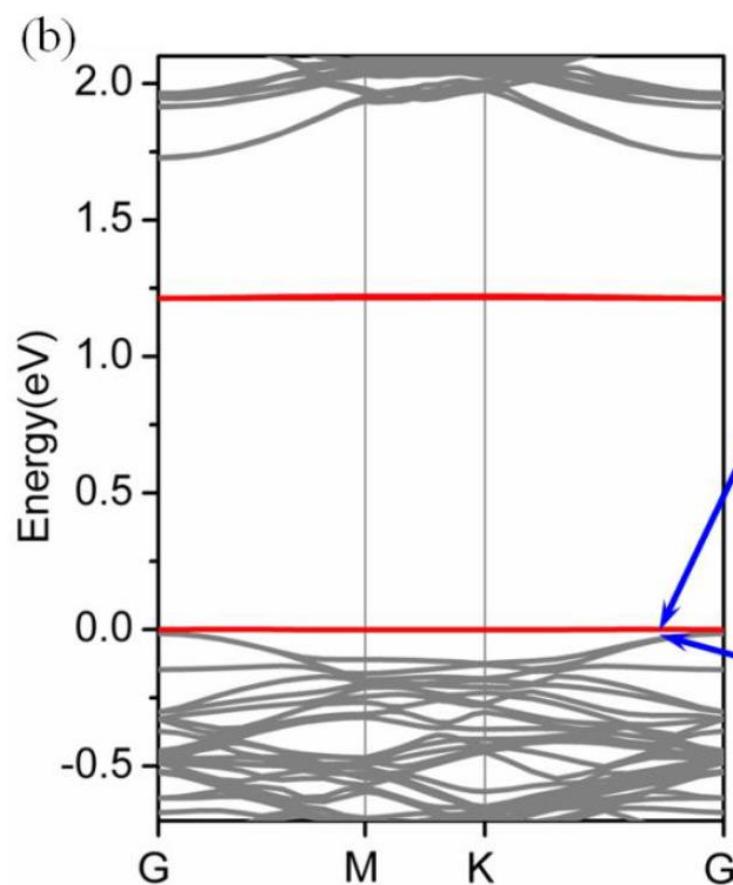
$\text{S2}_{\text{Mo}}$

# Atomic and electronic structure of V<sub>S</sub>

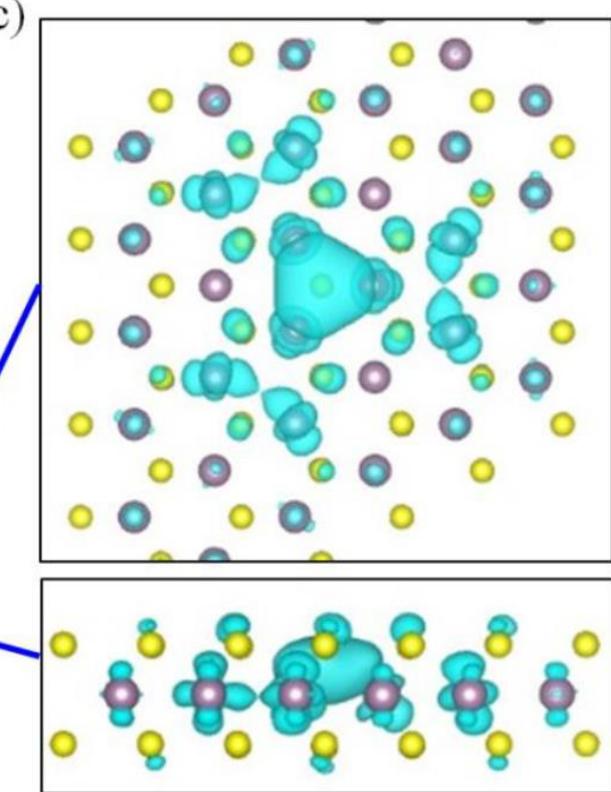
TEM image and structural model



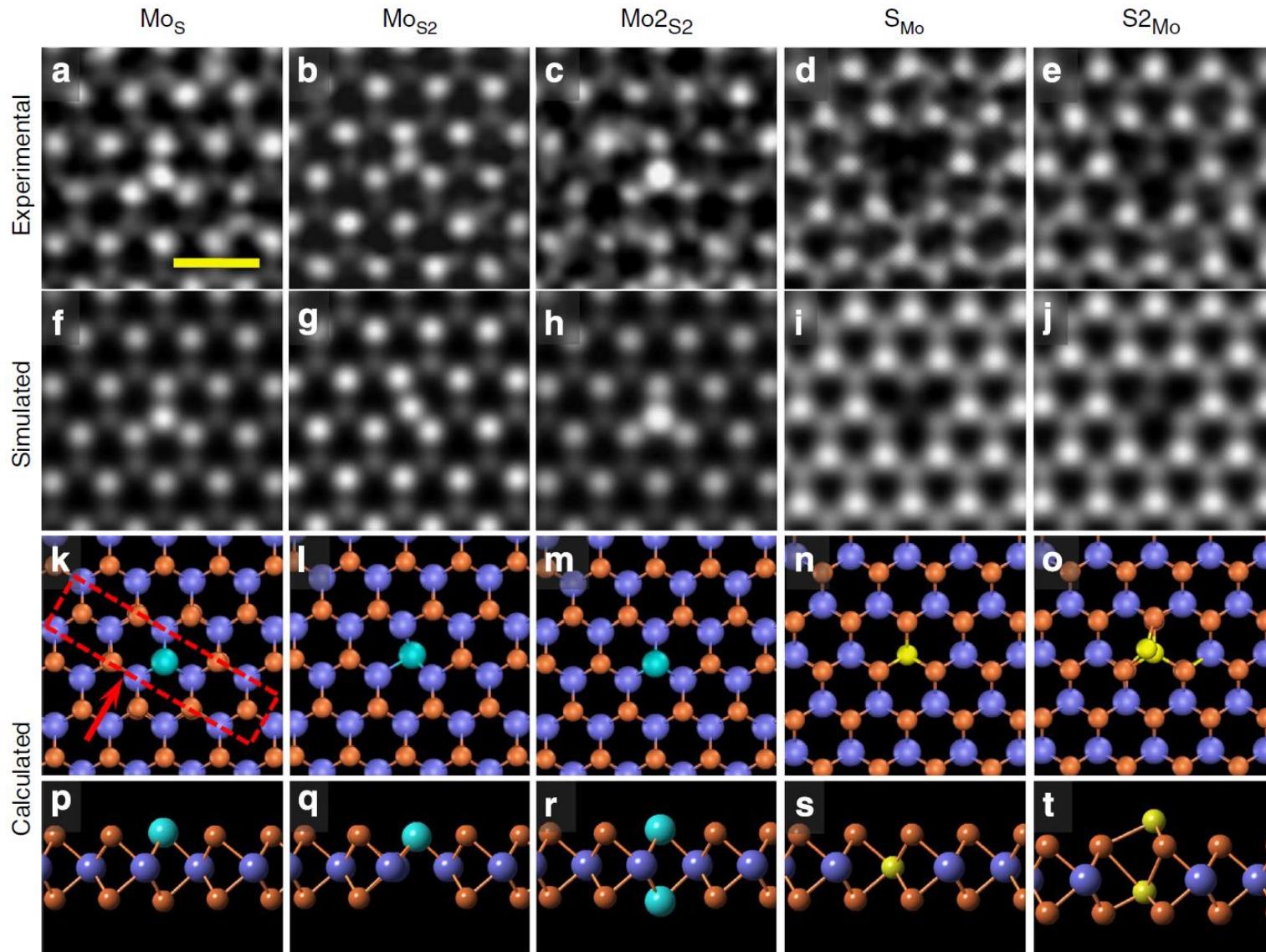
Band structure



Defect state wavefunction



# Antisite defects in $\text{MoS}_2$



# Defect formation energy and concentration

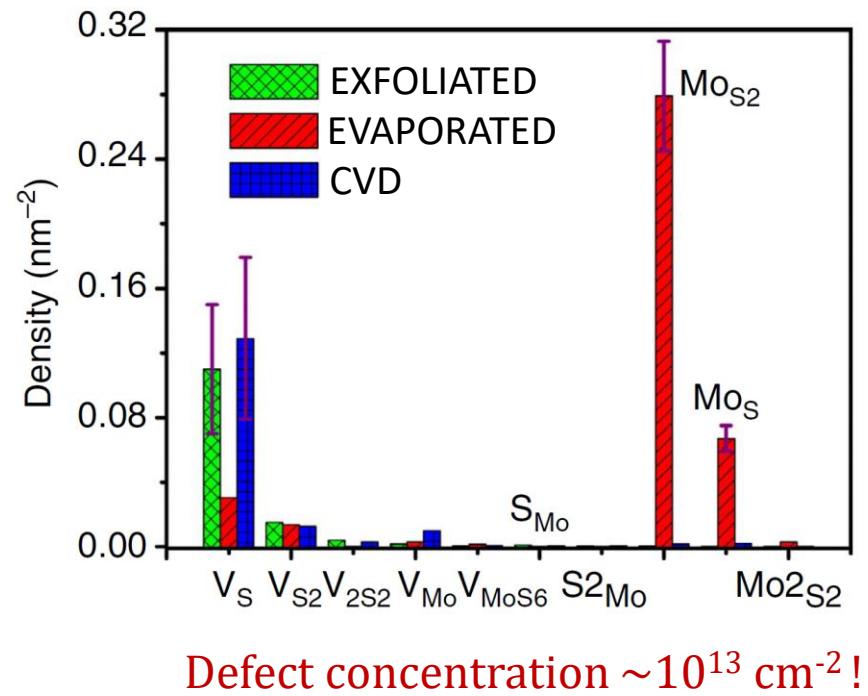
**Table 1 | Formation energy ( $\Delta E_{\text{Form}}$ ) and enthalpy ( $\Delta H_{\text{Form}}$ ) of considered point defects.**

	CASTEP	VASP	
	$\Delta H_{\text{Form}}(\text{eV})$	$\Delta H_{\text{Form}}(\text{eV})$	$\Delta E_{\text{Form}}(\text{eV})$
Mo <sub>S</sub>	6.22 ~ 7.29	5.45 ~ 6.09	5.79
Mo <sub>2</sub> S <sub>2</sub>	11.15	7.95	7.54
Mo <sub>2</sub> S <sub>2</sub>	—	9.81 ~ 11.09	10.49
S <sub>Mo</sub>	6.65 ~ 5.58	6.11 ~ 5.47	5.77
S <sub>2</sub> <sub>Mo</sub>	8.00	7.09	7.49
V <sub>S</sub>	2.74 ~ 1.67	2.86 ~ 2.22	2.12
V <sub>S2</sub>	—	5.63 ~ 4.34	4.14
V <sub>Mo</sub>	6.98 ~ 4.84	7.28 ~ 5.99	6.20

CASTEP, Cambridge Sequential Total Energy Package; VASP, Vienna *Ab-initio* Simulation Package.

The formation enthalpy is defined as  $\Delta H_{\text{Form}} = E_{\text{Defect}} - E_{\text{Pure}} + n \times \mu_{\text{Removed}} - m \times k\mu_{\text{Added}}$ .  $\mu$  is the chemical potential of the removed and/or added atom to form a defect, while the formation energy is defined as  $\Delta E_{\text{Form}} = E_{\text{System}} - N_{\text{S}} \times E_{\text{S-ML}} - N_{\text{Mo}} \times E_{\text{Mo-ML}}$ , where  $E_{\text{S-ML}}$  and  $E_{\text{Mo-ML}}$  are the single atom energy of Mo and S in a perfect monolayer. (Please refer to the Methods section for more details).

Different exchange-correlation functionals are used in the VASP and CASTEP codes as discussed in the text.



Hong et al., Nature Communications (2015)

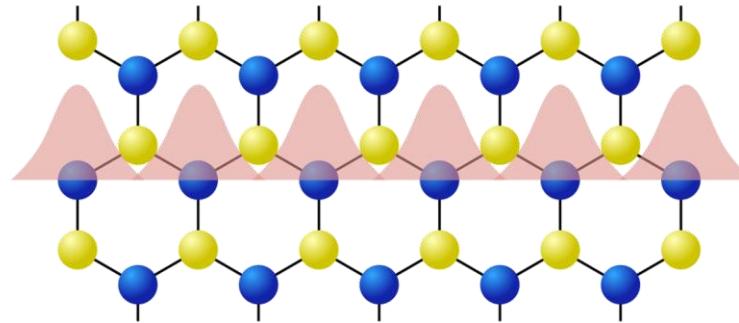
$$N_V = N_S e^{-(\Delta E_{\text{Form}} / k_B T)}$$

$N_V$	vacancy concentration
$N_S$	number of lattice sites
$T$	temperature
$k_B$	Boltzmann constant
$\Delta E_{\text{Form}}$	defect formation energy

# Transport in a disordered semiconductor

Perfect semiconductor:

- Delocalized charge carriers
- Band transport

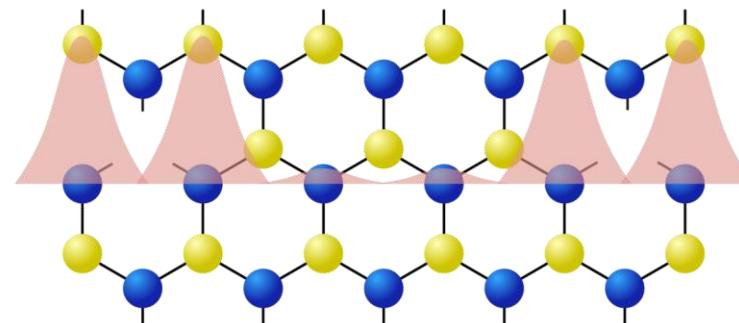


Electrical conductivity:

$$\sigma = \sigma_0 e^{-(E_A/k_B T)}$$

Disordered semiconductor:

- Trapped charges
- Localisation
- Hopping transport



*With four parameters I can fit an elephant, and with five I can make him wiggle his trunk.*

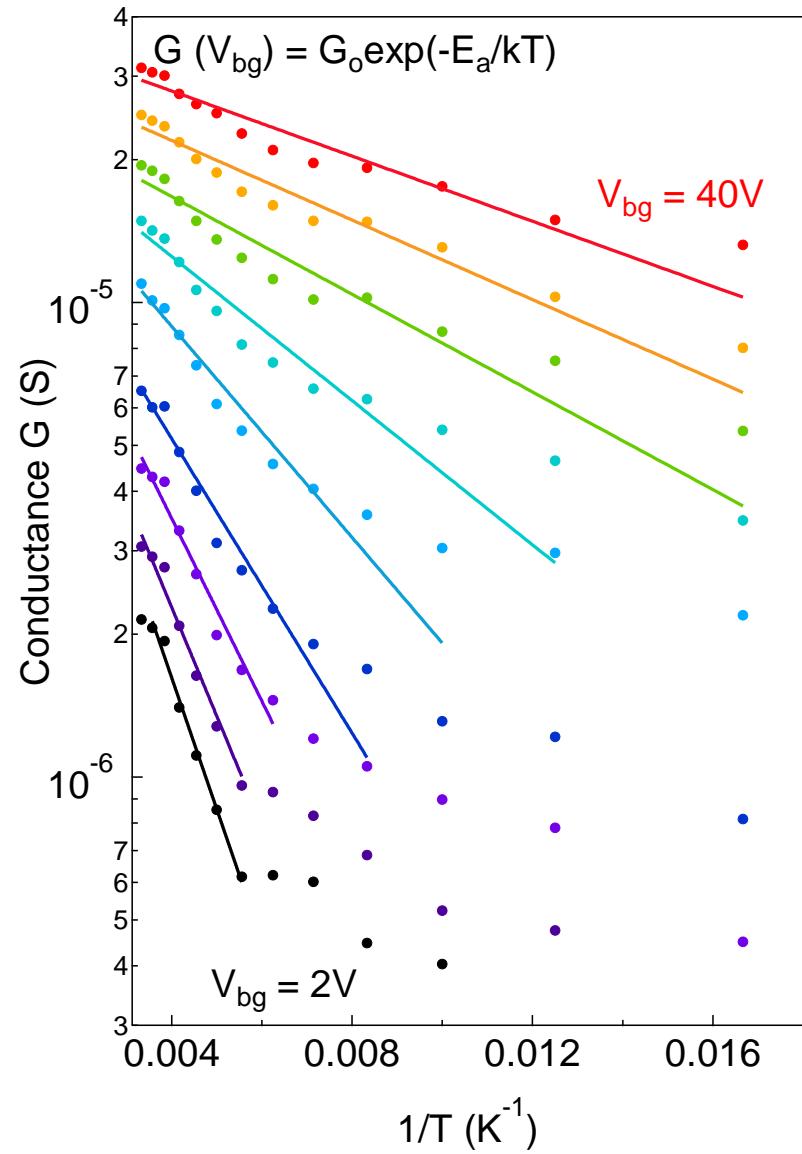
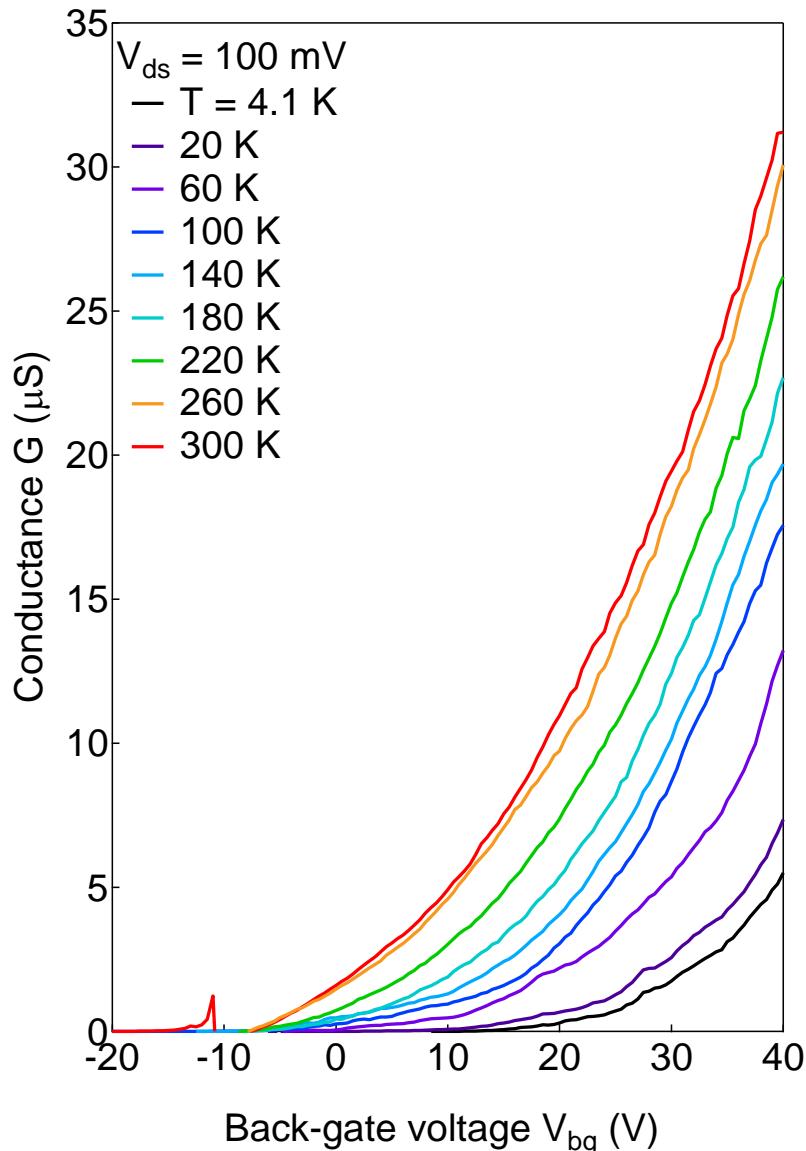
- John von Neumann

$$\sigma = \sigma_0 e^{-(T_0/T)^\beta}$$

$\sigma$  electrical conductivity  
 $T$  temperature  
 $k_B$  Boltzmann constant  
 $E_A$  activation energy  
 $T_0, \beta$  fitting parameters

# Temperature-dependent electrical transport in MoS<sub>2</sub>

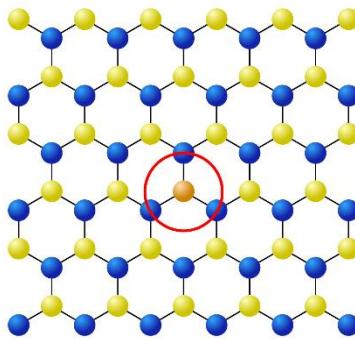
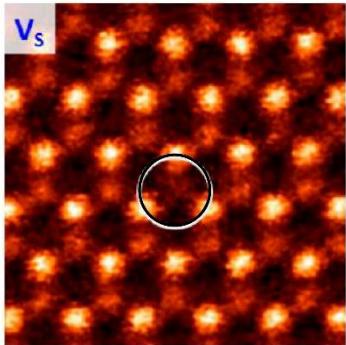
No top-gate dielectric



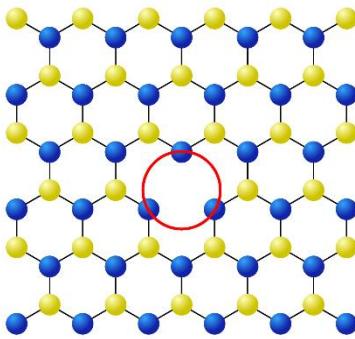
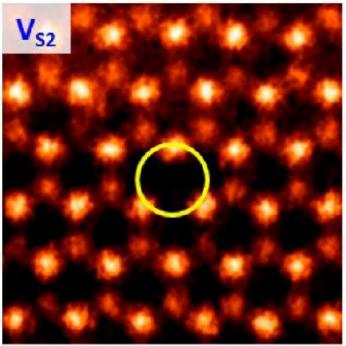
Radisavljevic and Kis; Nature Materials (2013)

# Most common point defects in $\text{MoS}_2$

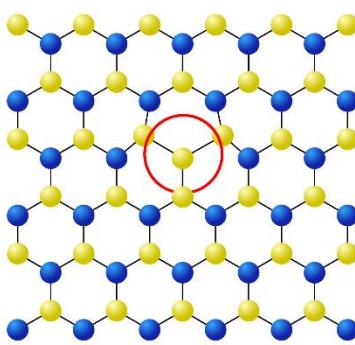
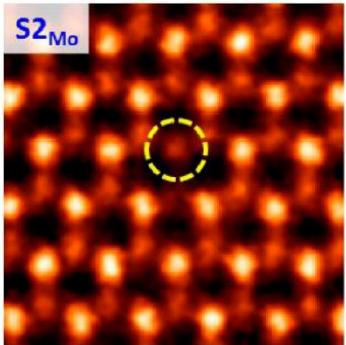
$\text{V}_\text{S}$



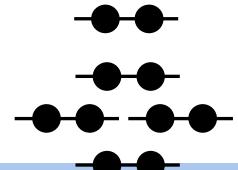
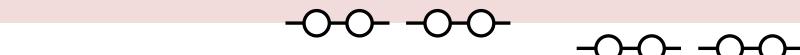
$\text{V}_{\text{S}2}$



$\text{S2}_{\text{Mo}}$



Conduction band



Valence band

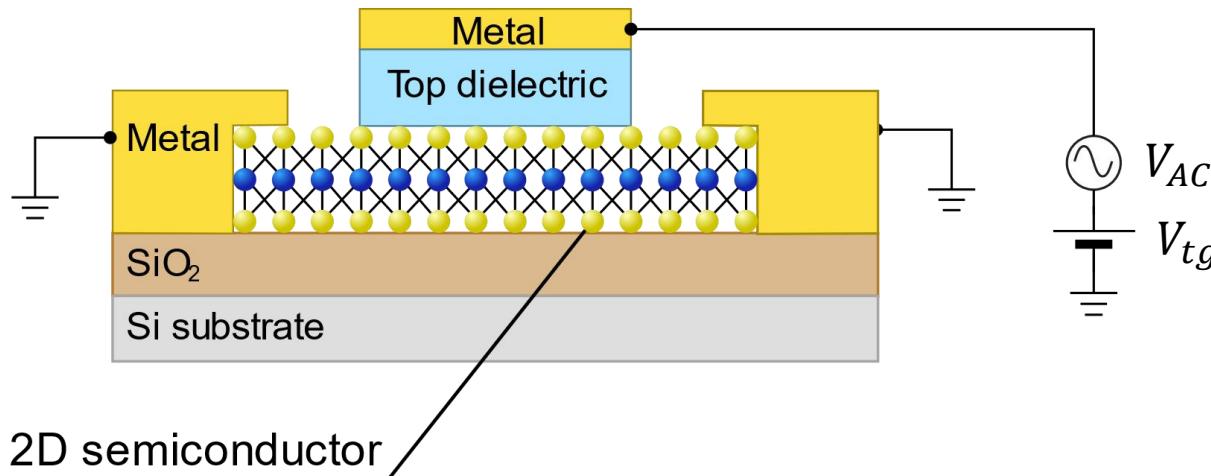


$\text{V}_\text{S}$

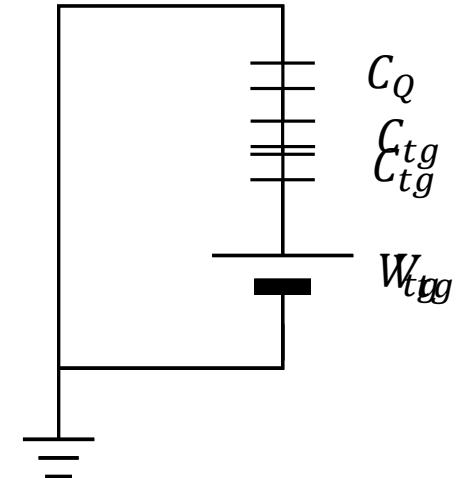
$\text{V}_{\text{S}2}$

$\text{S2}_{\text{Mo}}$

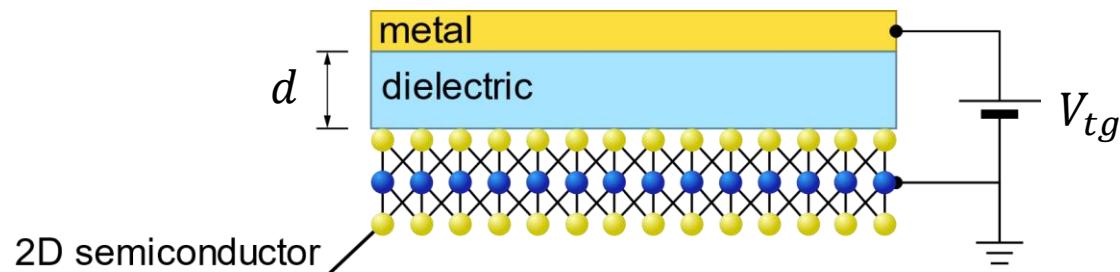
# Quantum capacitance



Equivalent circuit



Equivalent device: capacitor with the 2D material as one of the electrodes



$$C_{tg} = \frac{S\epsilon}{d} \quad \text{Geometric capacitance}$$

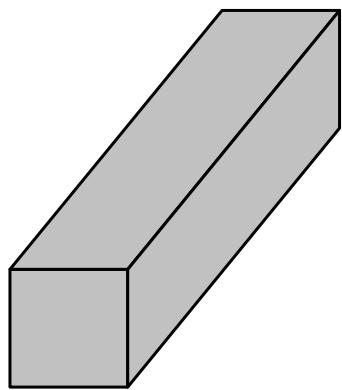
$$C_Q = e^2 \cdot DOS \quad \text{quantum capacitance}$$

For  $C_{tg} \gg C_Q$ ,  $C_Q$  dominates

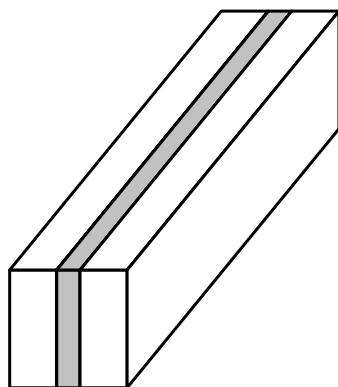
$$C_Q = \frac{2em^*}{\pi\hbar^2} \quad \text{for 2D inside the 1st subband}$$

# Repeated from 2.1: Dimensions in Semiconductor Physics

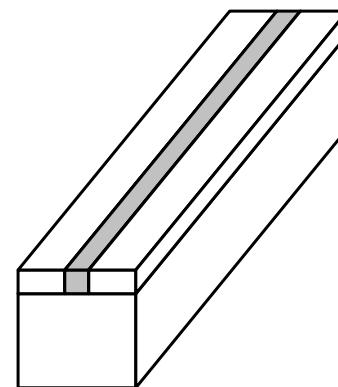
3D



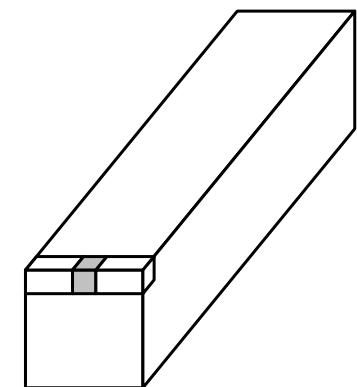
2D



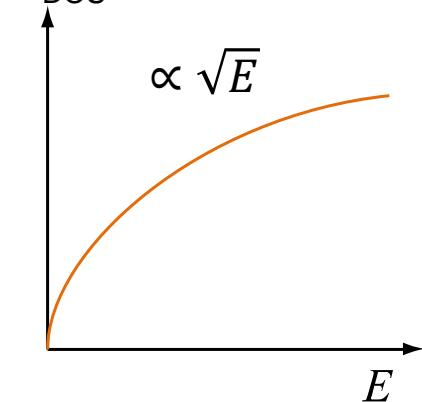
1D



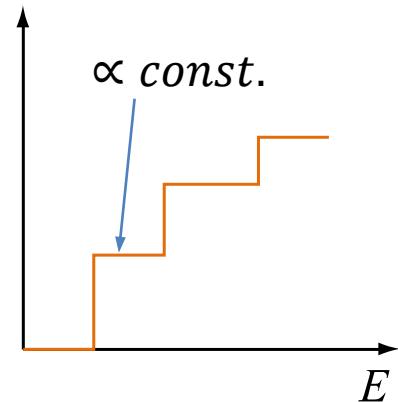
0D



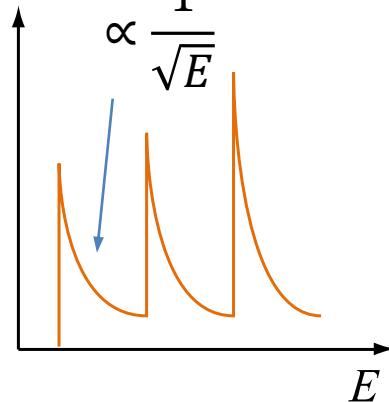
$\rho_{\text{DOS}}$



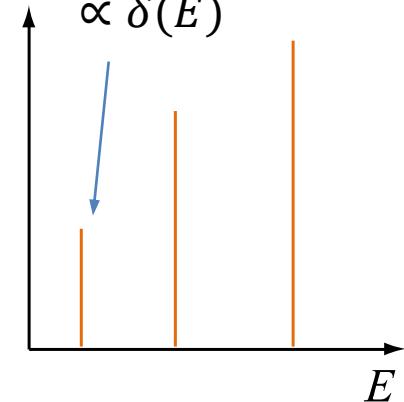
$\propto \text{const.}$



$\propto \frac{1}{\sqrt{E}}$

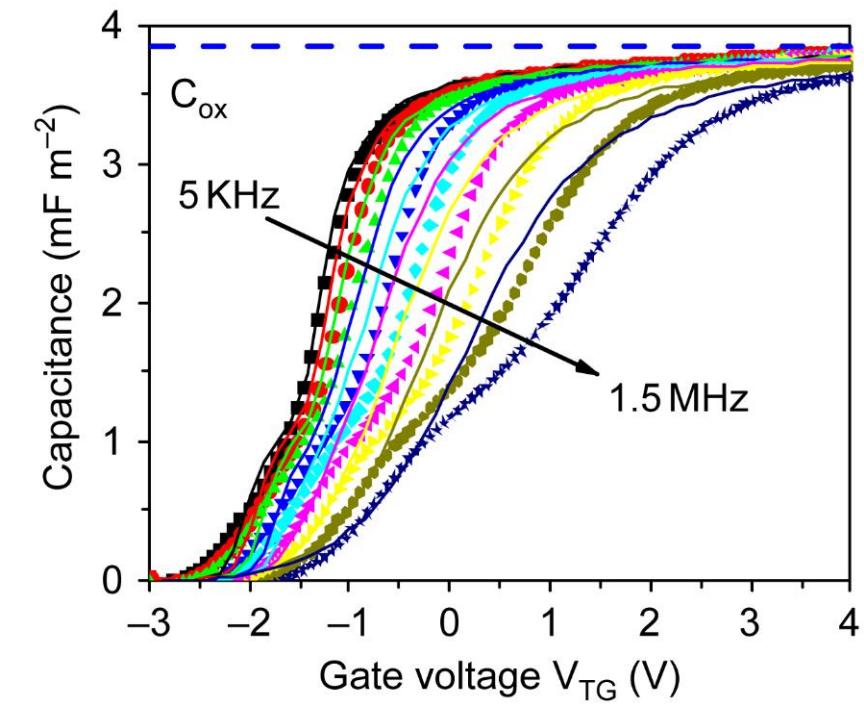
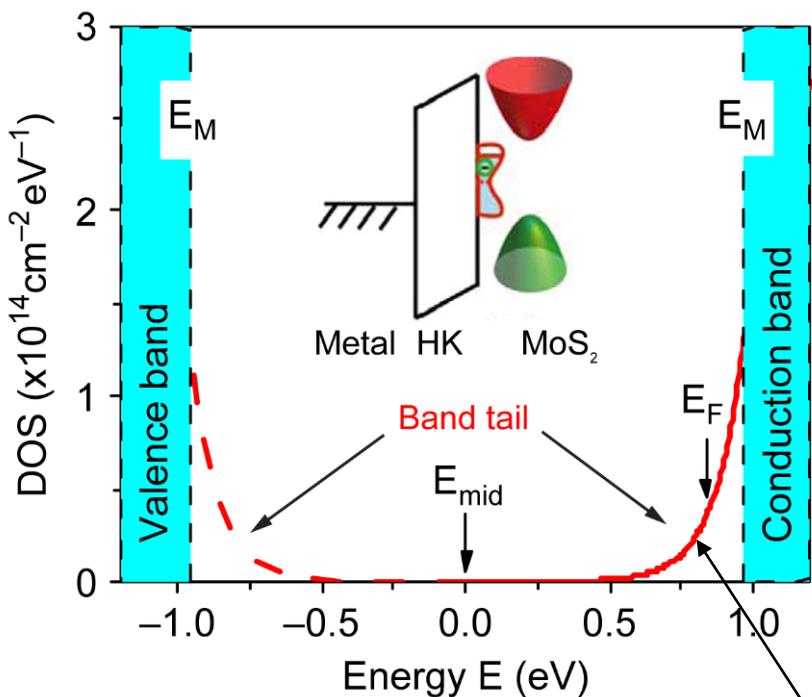
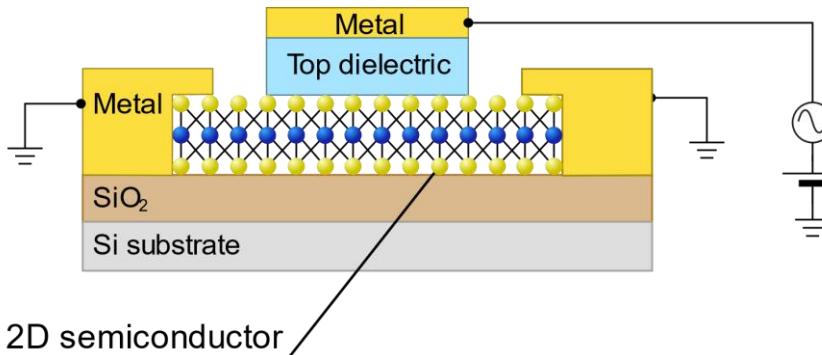


$\propto \delta(E)$



assuming  $E = \frac{\hbar^2 k^2}{2m}$

# Capacitance - voltage measurements

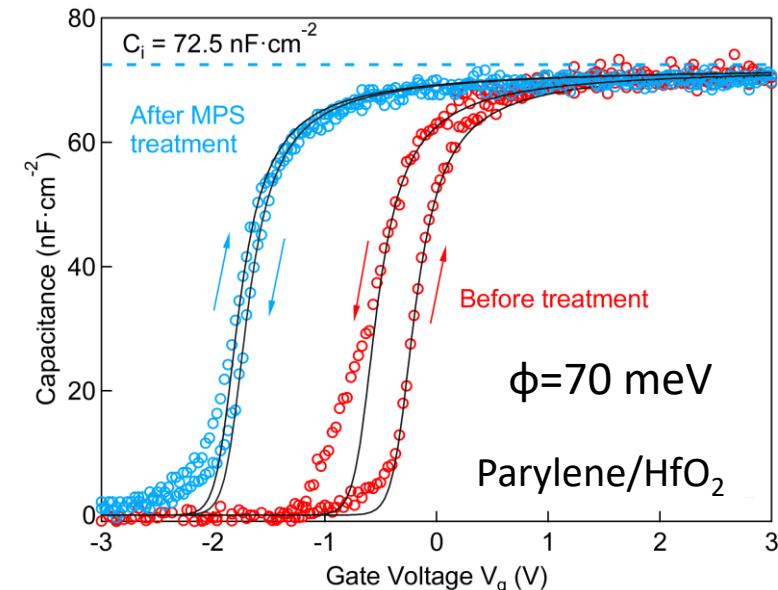
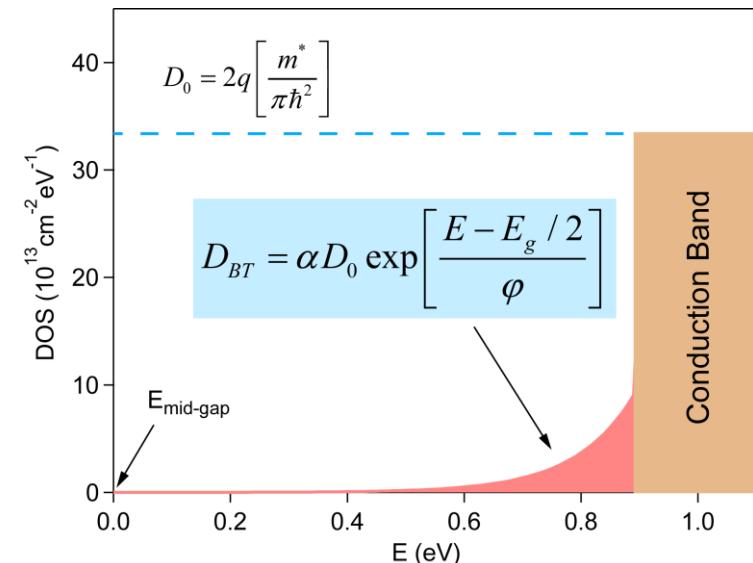
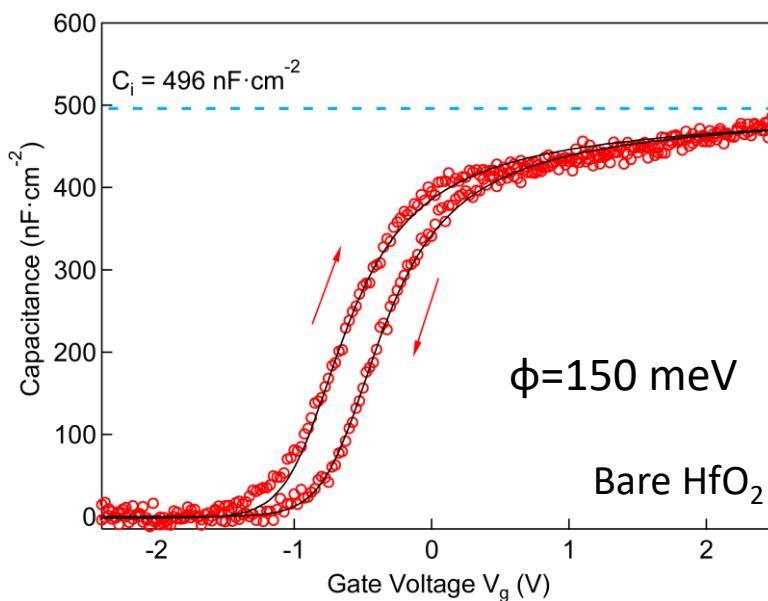
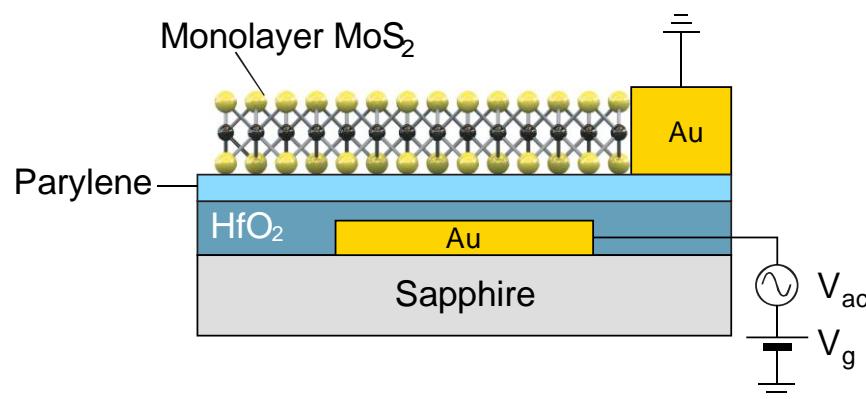


Zhu et al., Nature Communications (2014)

$$D_{BT} = \alpha D_0 \exp \left[ \frac{E - E_g/2}{\varphi} \right]$$

$\varphi \approx 100 \text{ meV}$

# CV measurements



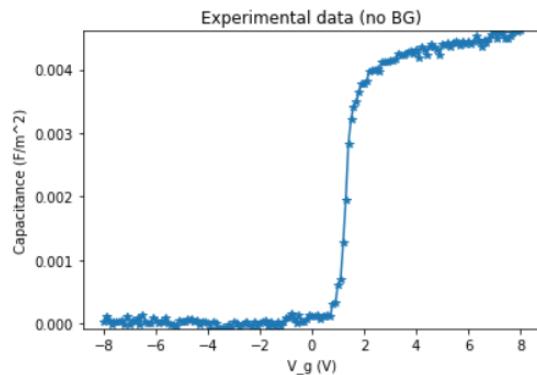
# CV measurements – parameter extraction

## → Exercise session

Remove background and define  $C_i = C_{max}$

```
In [34]: idx1 = np.where(Vg_ex == -3)
idx2 = np.where(Vg_ex == -1)
idx1 = int(idx1[0])
idx2 = int(idx2[0])
Cgch_ex = Cgch_ex - np.mean(Cgch_ex[idx1:idx2]); # Remove background for better fitting, cbgd = average between -3V and -1V
idx3 = np.where(Vg_ex == 3) # find index of V = 3V for maximum capacitance value Ci = Cmax
idx3 = int(idx3[0])
Ci=Cgch_ex[idx3];
```

```
In [35]: plt.plot (Vg_ex,Cgch_ex,'-*')
plt.xlabel('V_g (V)')
plt.ylabel('Capacitance (F/m^2)')
plt.title('Experimental data (no BG)');
plt.ylim([np.min(Cgch_ex),np.max(Cgch_ex)])
plt.show()
plt.close()
```



#Cg Fit

# Mitigation strategies - overview

Various strategies for reducing the impact of point defects:

- Dielectric environment (encapsulation)
- Chemical treatment

# Dielectric environment

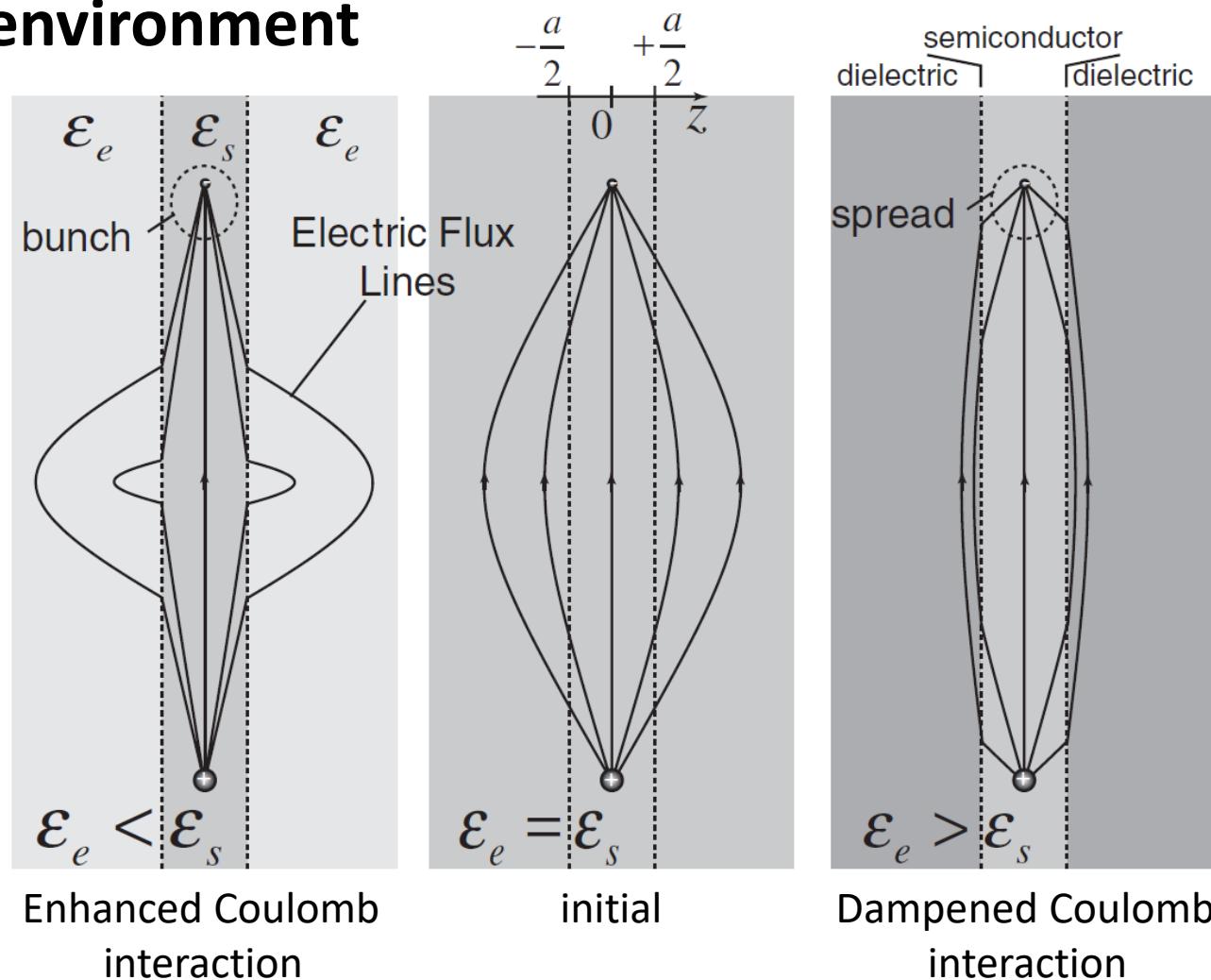
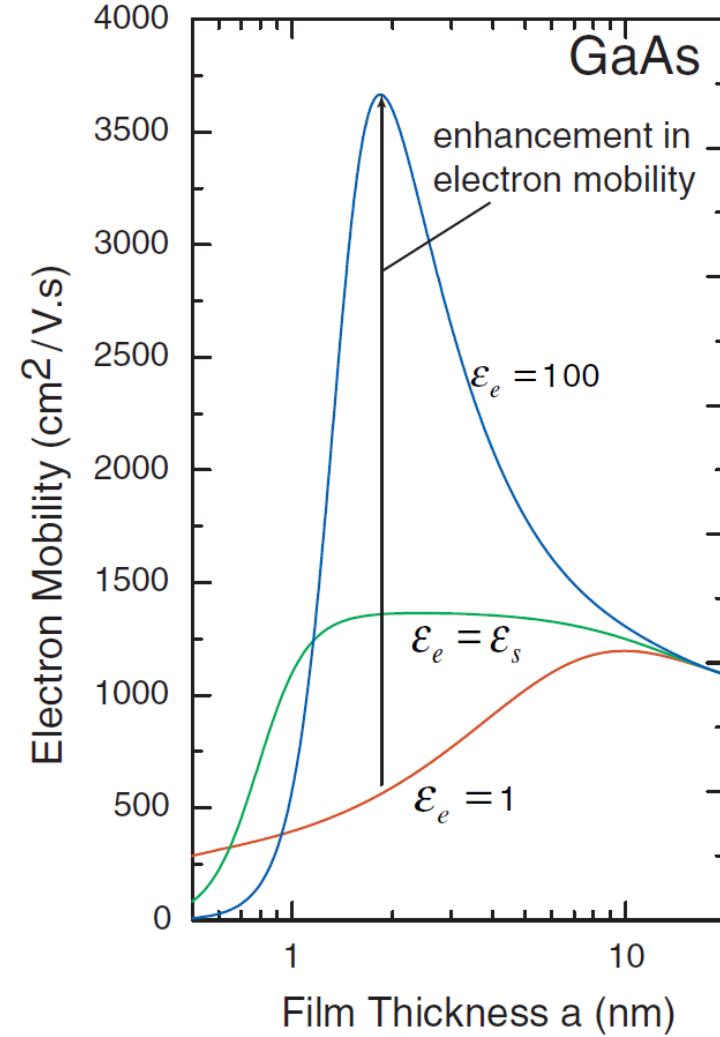
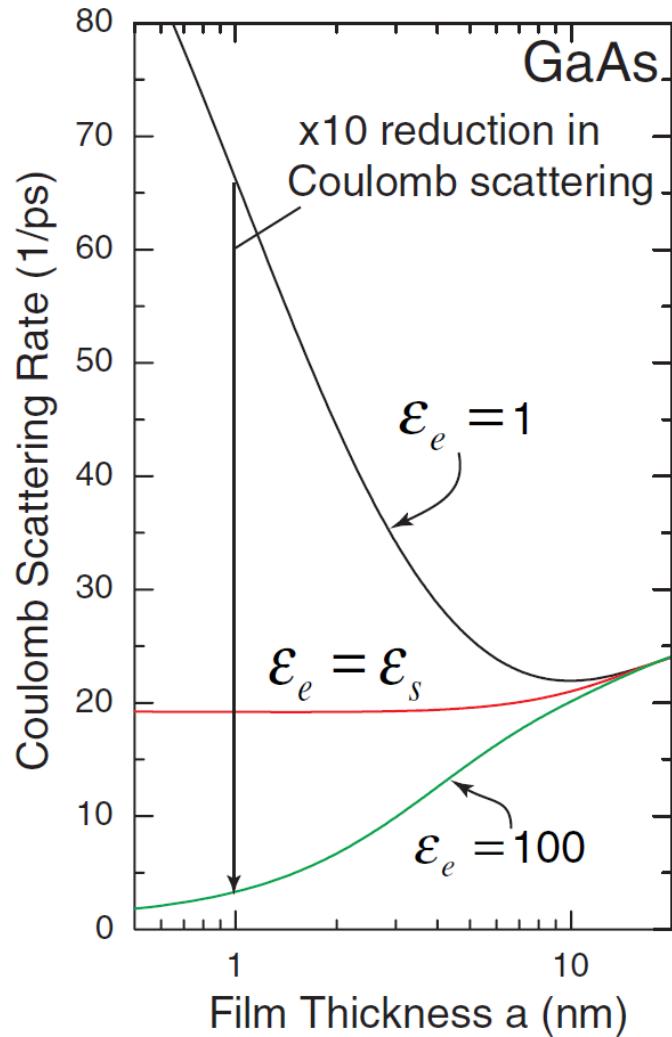


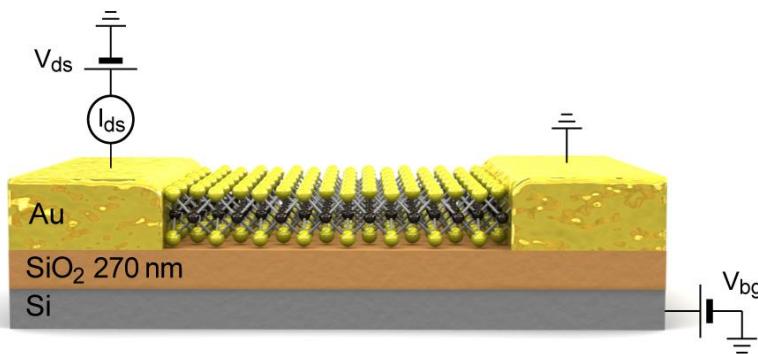
FIG. 1. Electric flux lines originating from a fixed ionized impurity and terminating on a mobile electron, and the effect of the dielectric environment. The flux lines bunch closer inside the semiconductor layer if  $\epsilon_e < \epsilon_s$ , and spread farther apart if  $\epsilon_e > \epsilon_s$ , thus enhancing Coulomb interaction in the former case and damping it in the latter.

# Dielectric environment

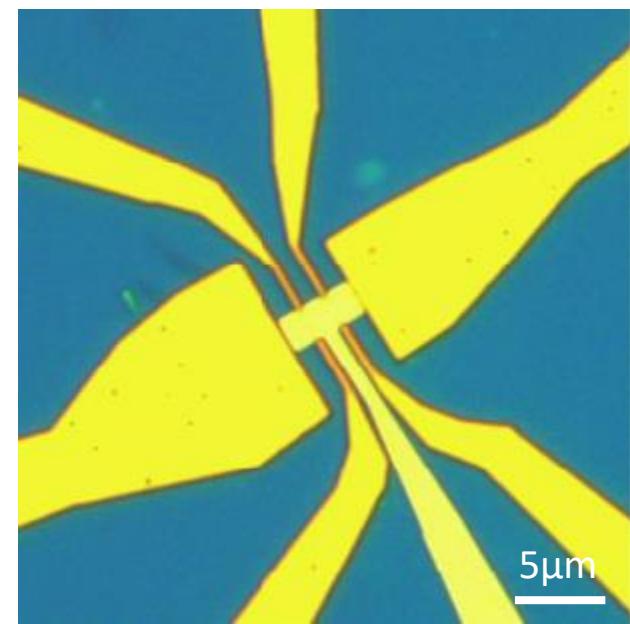
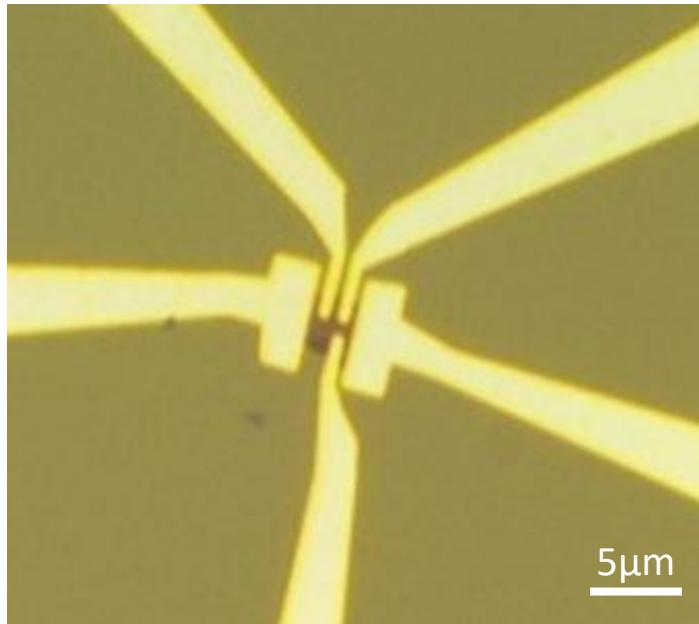
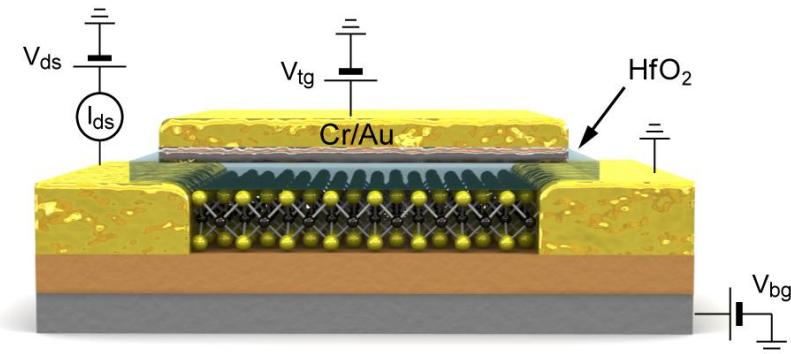


# Temperature-dependent electrical transport

No top-gate dielectric

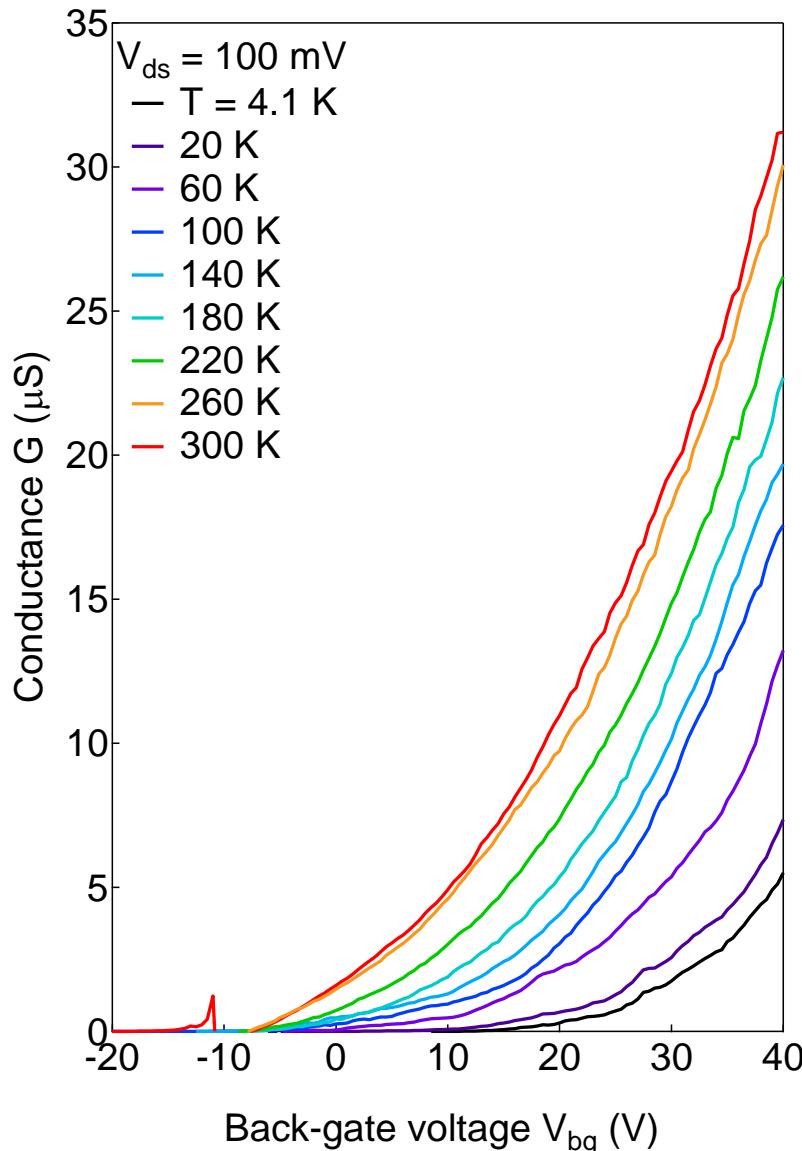


With top-gate dielectric

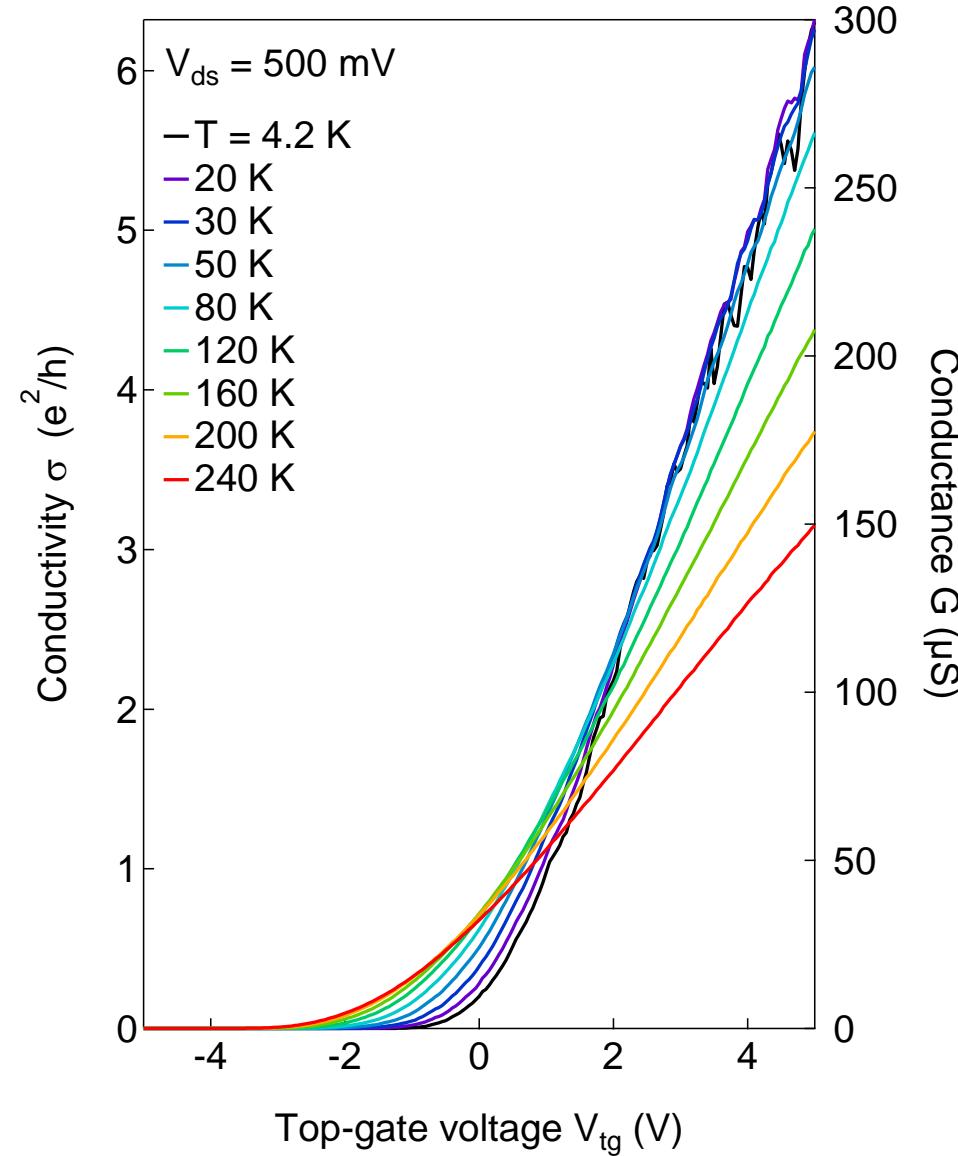


# Temperature-dependent electrical transport

No top-gate dielectric



With top-gate dielectric

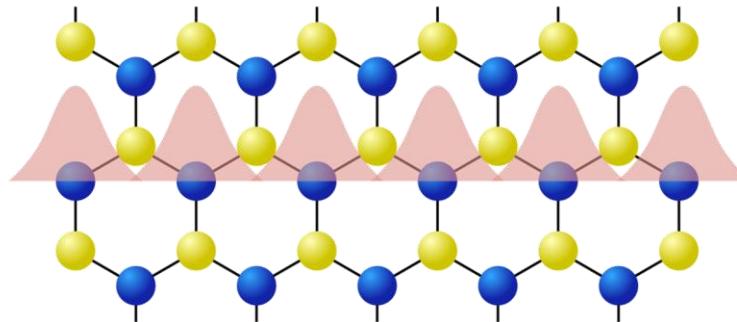


Radisavljevic and Kis; Nature Materials (2013)

# [RECAP] Transport in a disordered semiconductor

Perfect semiconductor:

- Delocalized charge carriers
- Band transport

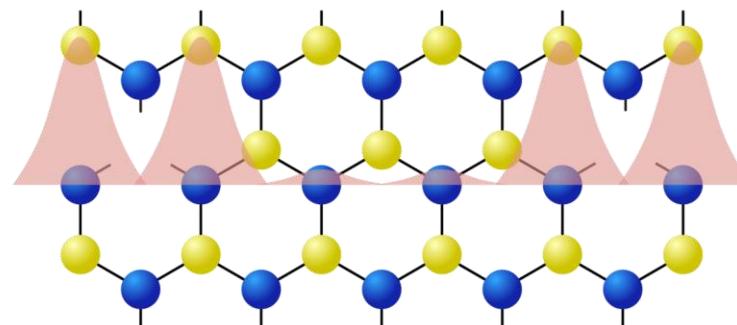


Electrical conductivity:

$$\sigma = \sigma_0 e^{-(E_A/k_B T)}$$

Disordered semiconductor:

- Trapped charges
- Localisation
- Hopping transport



*With four parameters I can fit an elephant, and with five I can make him wiggle his trunk.*

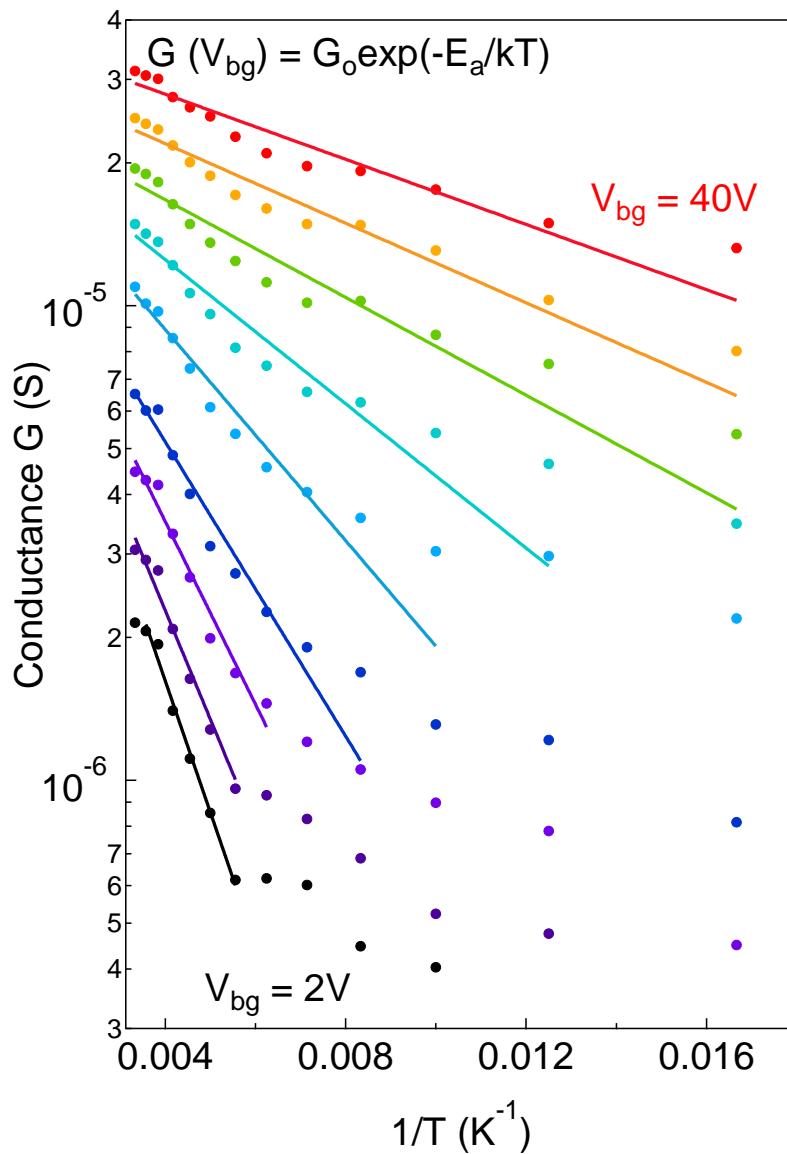
- John von Neumann

$$\sigma = \sigma_0 e^{-(T_0/T)^\beta}$$

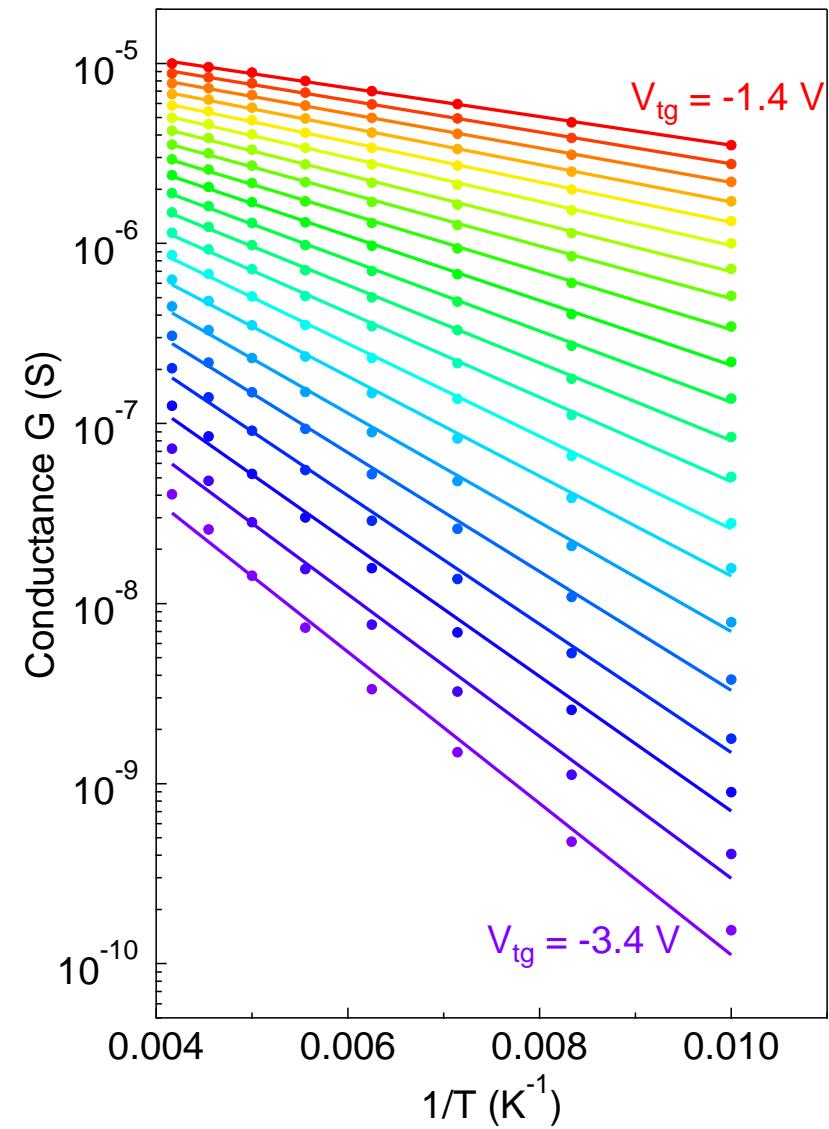
$\sigma$  electrical conductivity  
 $T$  temperature  
 $k_B$  Boltzmann constant  
 $E_A$  activation energy  
 $T_0, \beta$  fitting parameters

# Temperature-dependent electrical transport

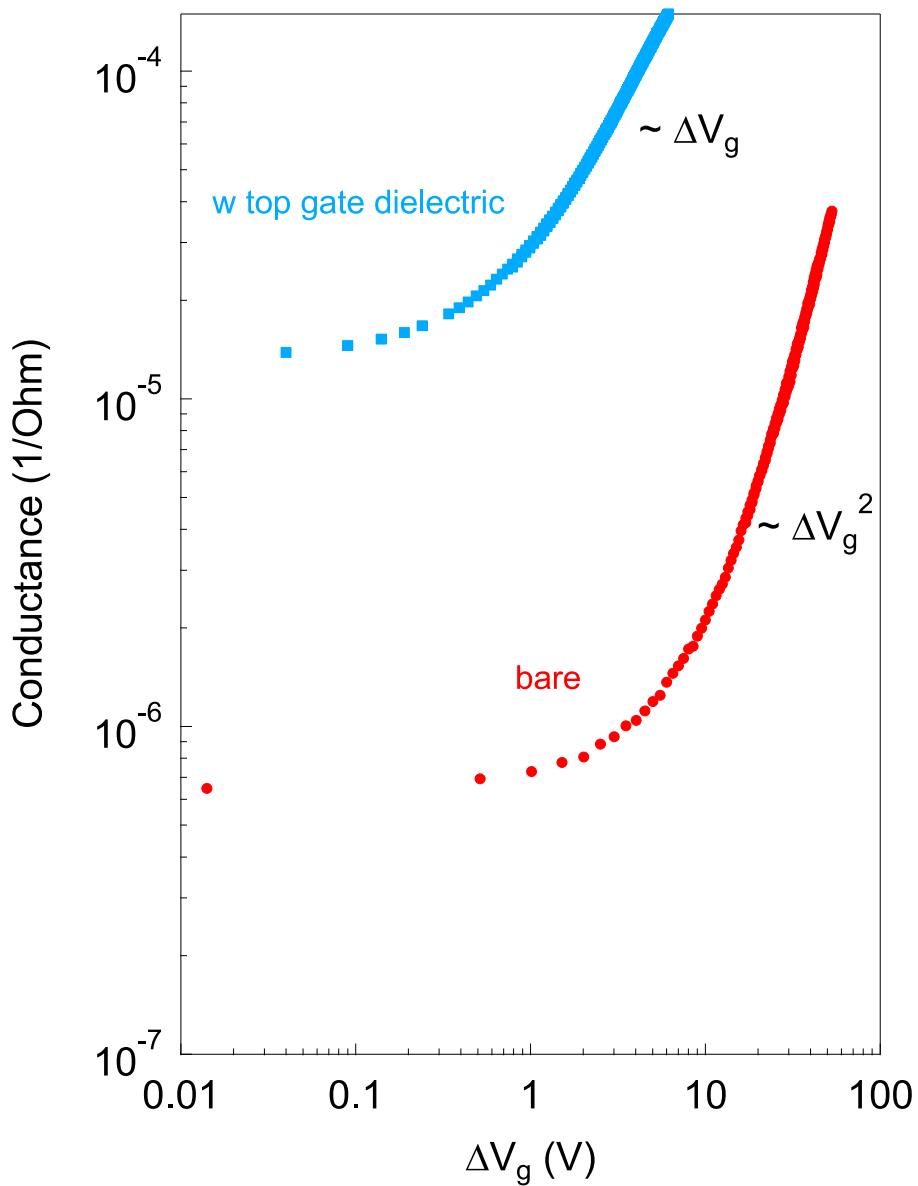
No top-gate dielectric



With top-gate dielectric



# Screened vs. unscreened disorder potential



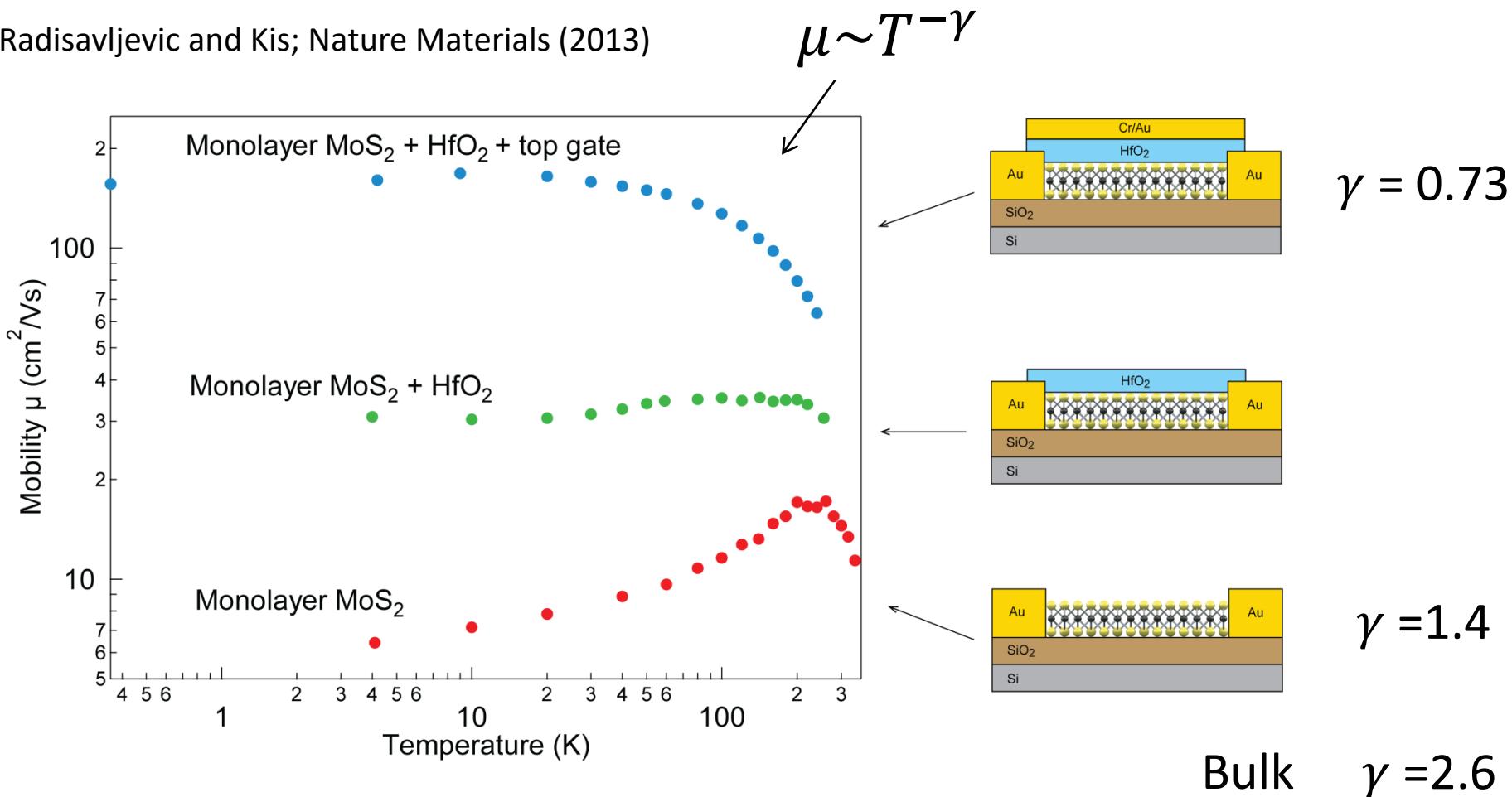
S. Adam and D. Sarma., PRB (2008):

$\sigma \sim n$  screened ch. impurities

$\sigma \sim n^2$  unscreened

# Mobility vs. temperature

Radisavljevic and Kis; Nature Materials (2013)



Calculations:

HP mode quenching

$\gamma = 1.5$  Kaasbjerg et al., PRB (2012)

HP mode quenching

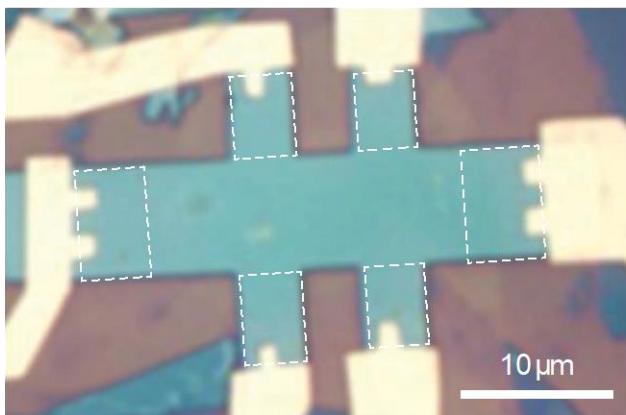
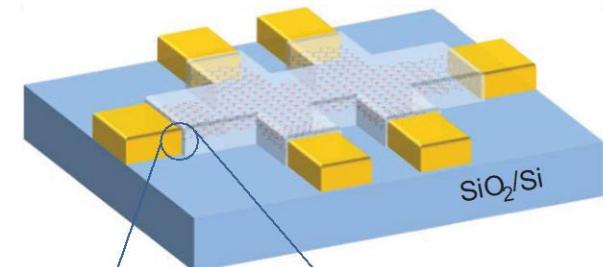
$\gamma = 1$  Kaasbjerg et al., PRB (2013)

HP mode quenching

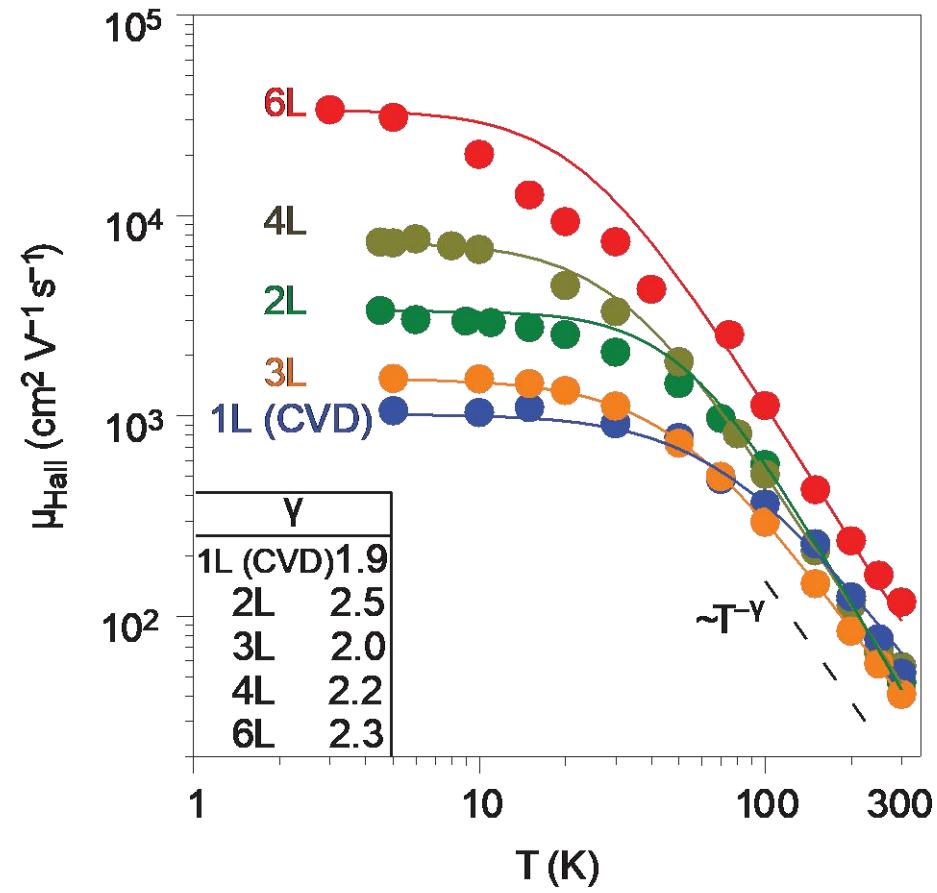
$\gamma = 0.5$  Ong and Fischetti, PRB (2013)

$T$  dep. of screening and CI scattering, TG screening

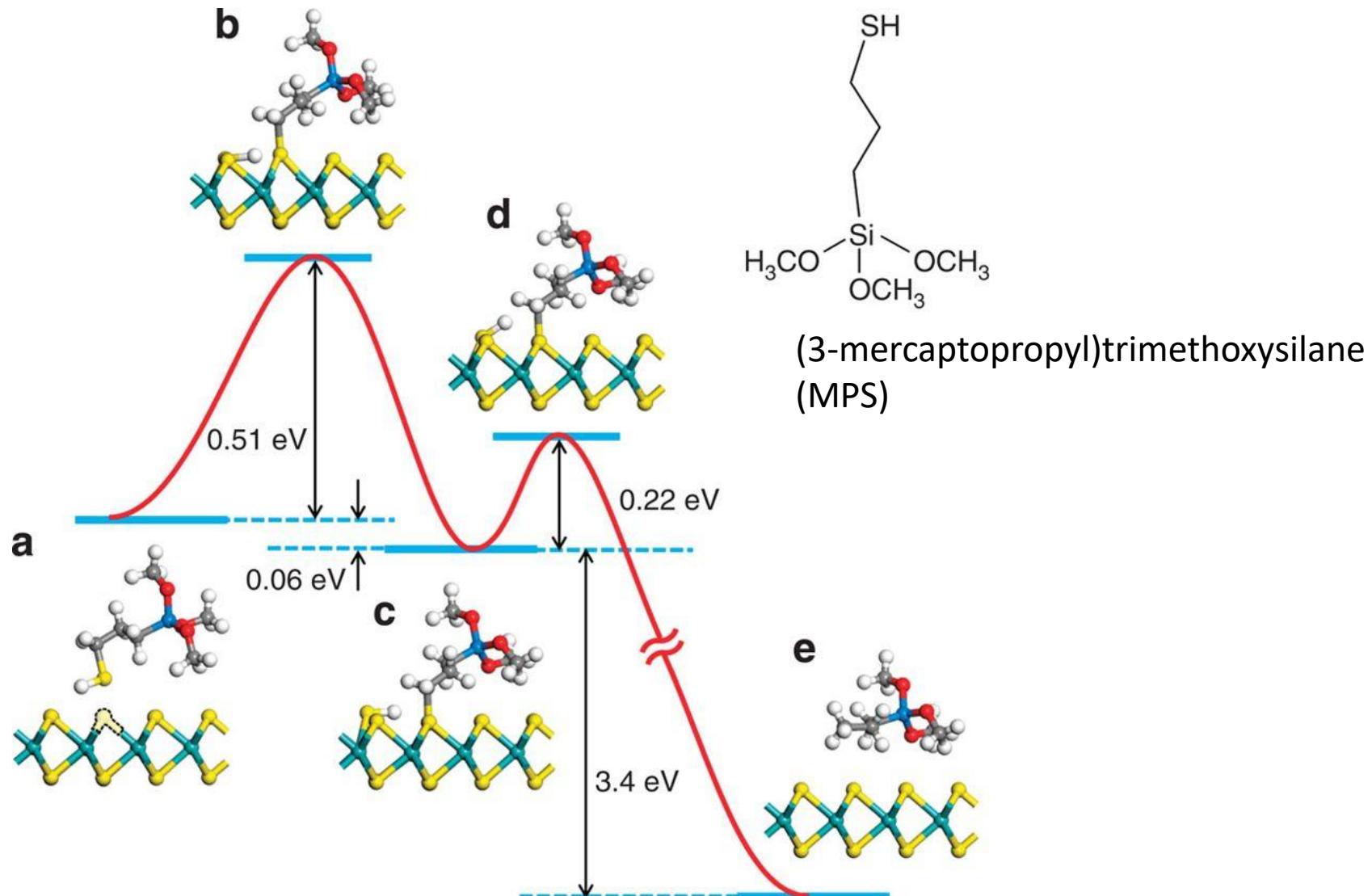
# Encapsulation in Boron Nitride



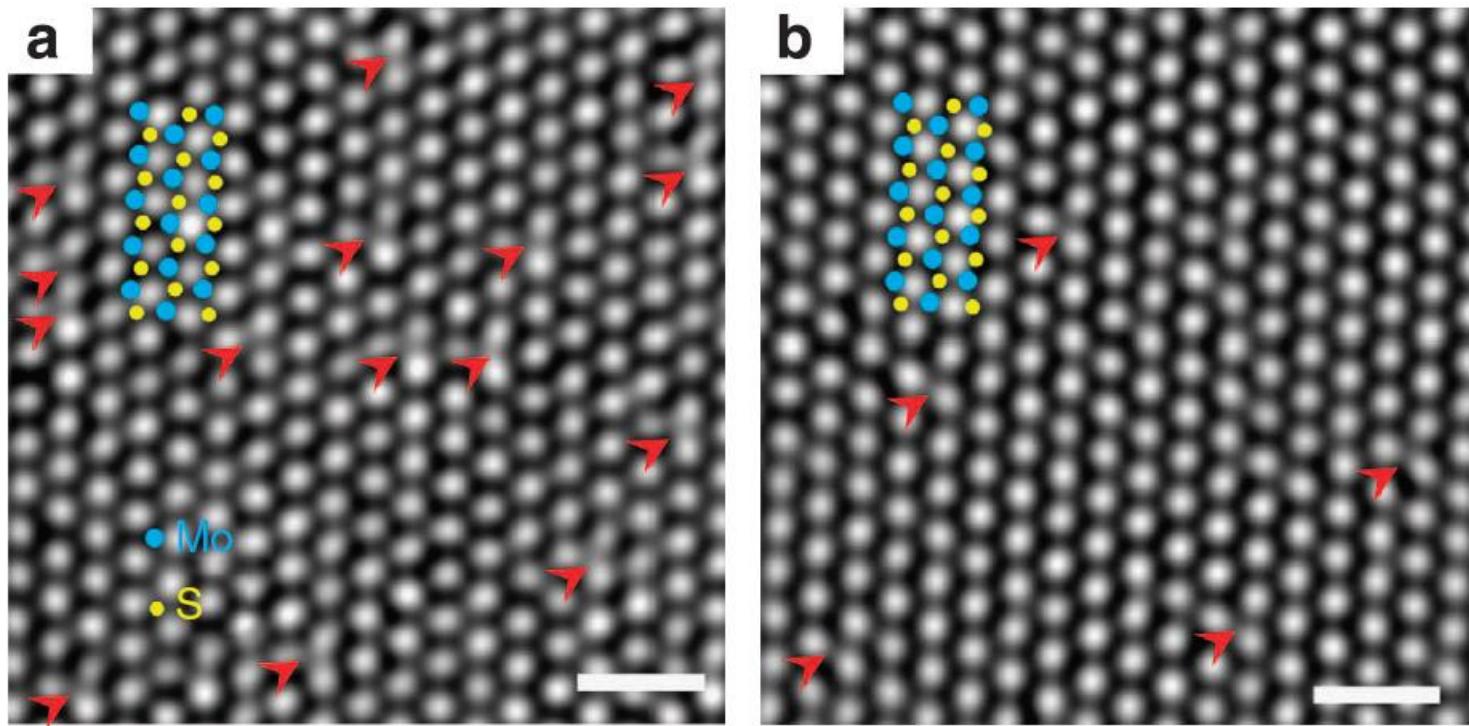
Cui...Hone; Nat. Nano (2015)



# Defect healing by chemical treatment: thiols



# Defect healing by chemical treatment: thiols

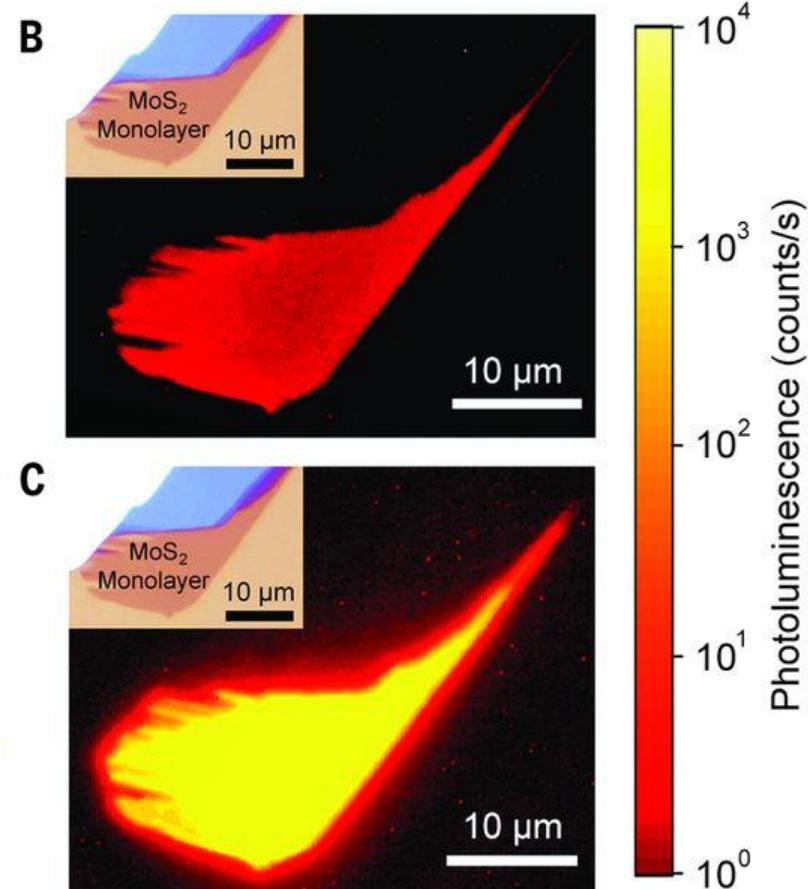
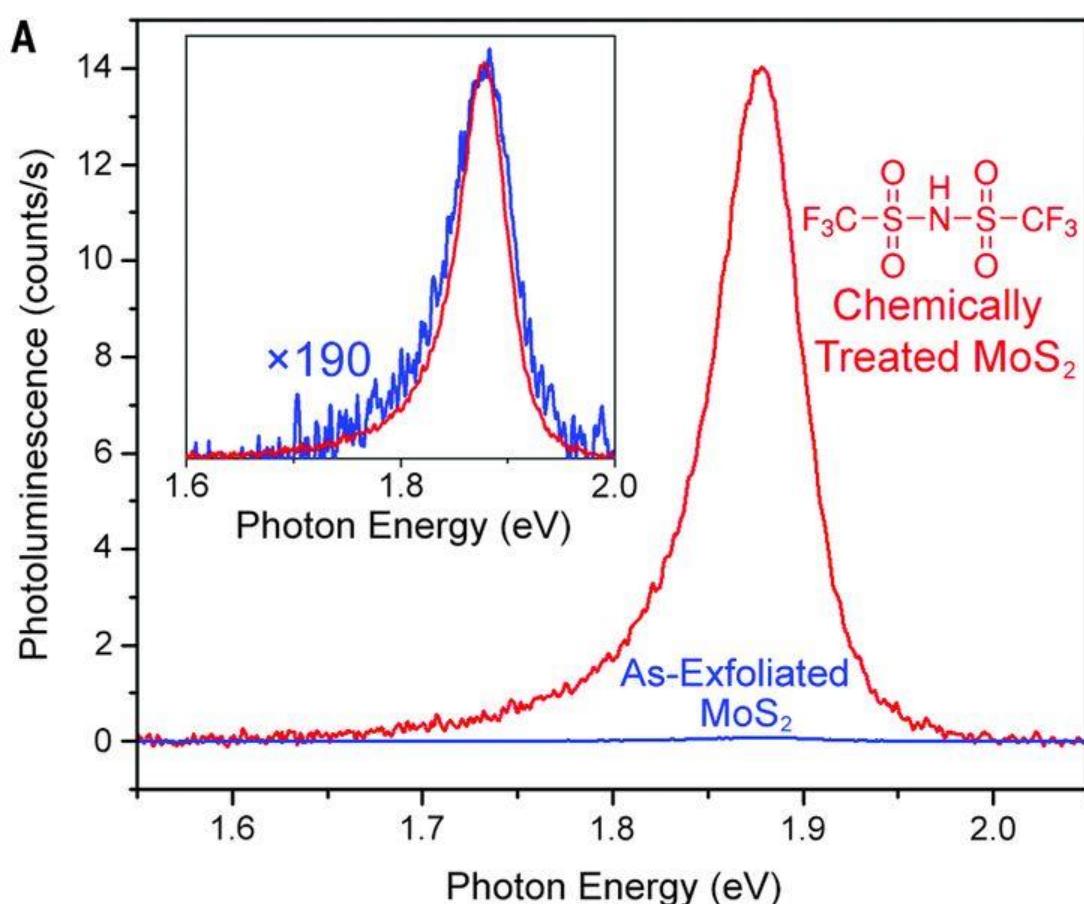


**Figure 2 | High-resolution aberration-corrected TEM images.**

**(a)** As-exfoliated and **(b)** TS-treated monolayer MoS<sub>2</sub> sample, showing the significant reduction of SV by MPS treatment. The SVs are highlighted by red arrows. The overlaid blue and yellow symbols mark the position of Mo and S atoms, respectively. Scale bar, 1 nm. Detailed intensity profile analysis and histogram of SV density are shown in Supplementary Fig. 9.

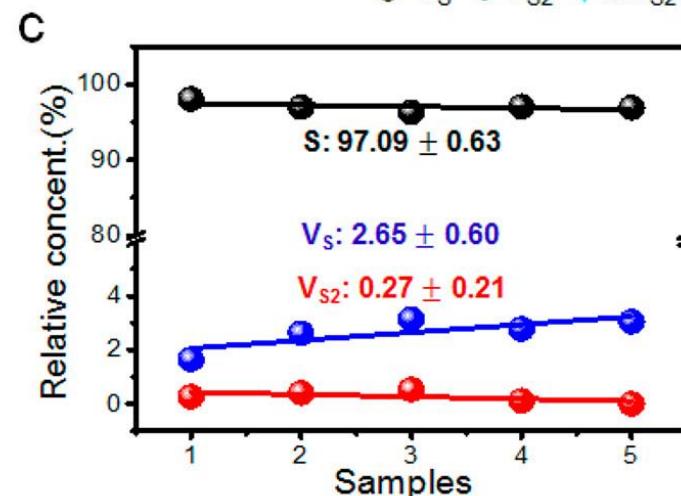
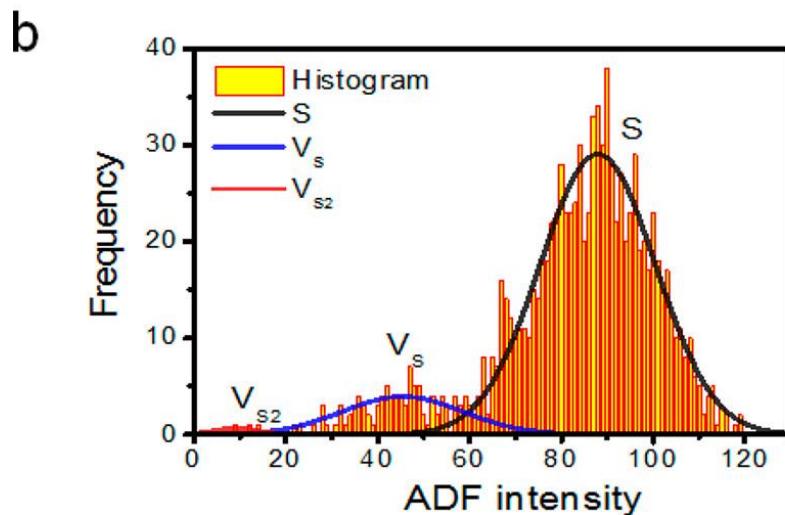
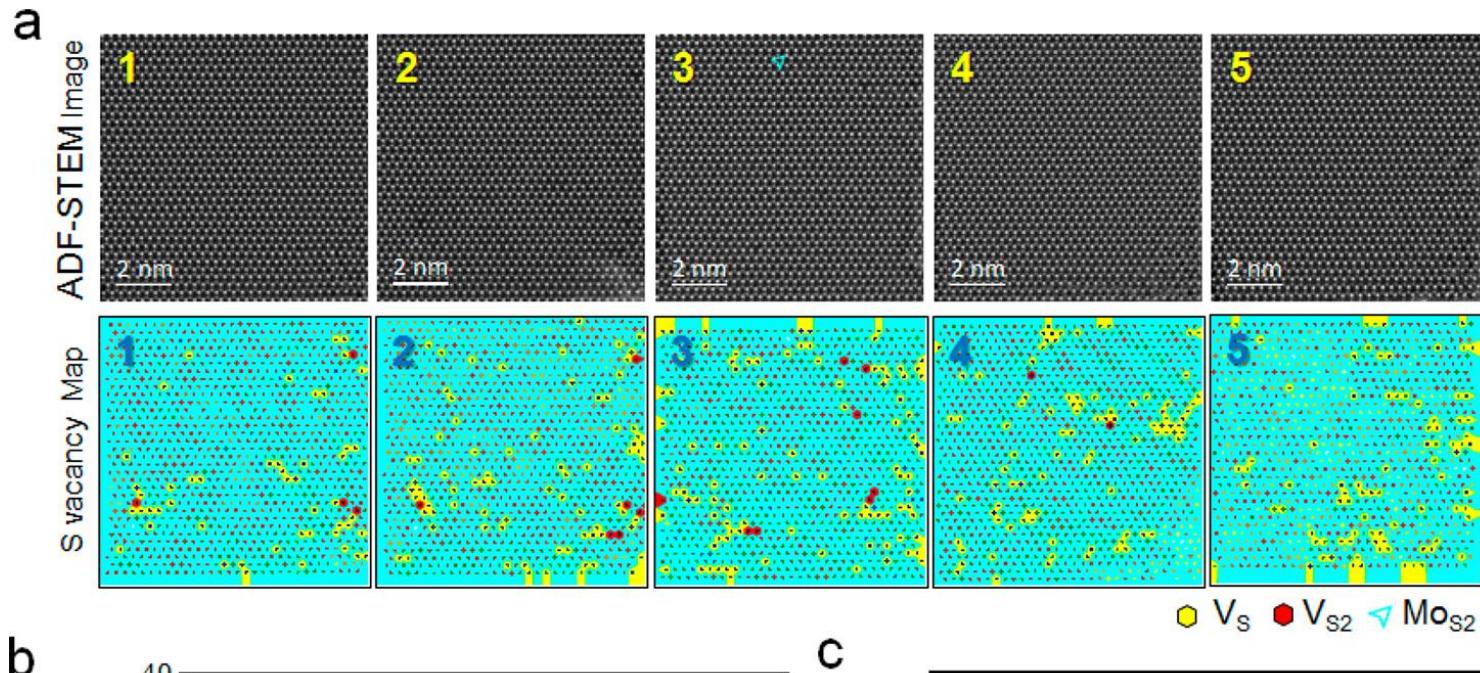
# Defect healing by chemical treatment: TFSI superacid

bis(trifluoromethane) sulfonimide (TFSI); stronger acidity than  $\text{H}_2\text{SO}_4$



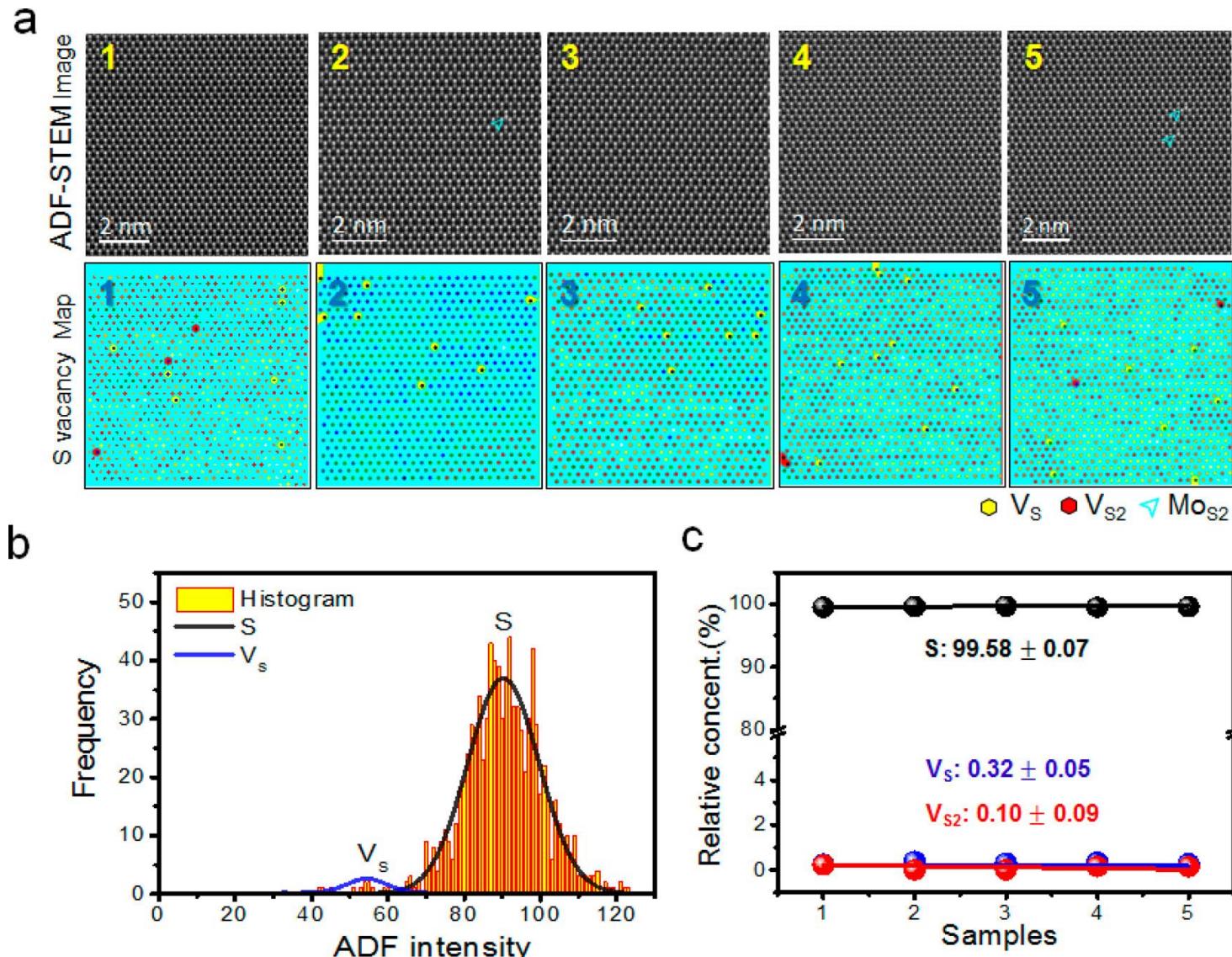
# Defect healing by chemical treatment: TFSI superacid

Before:

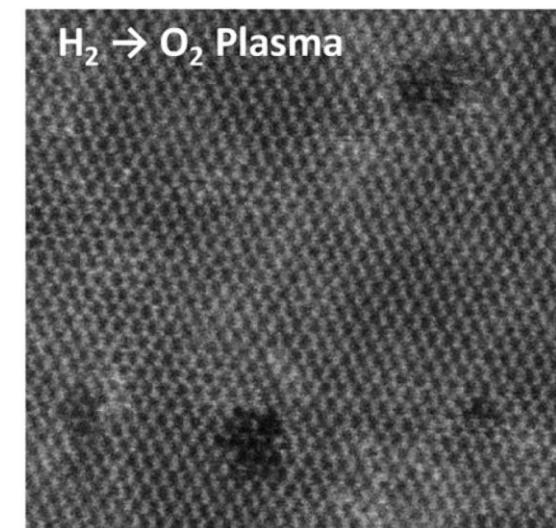
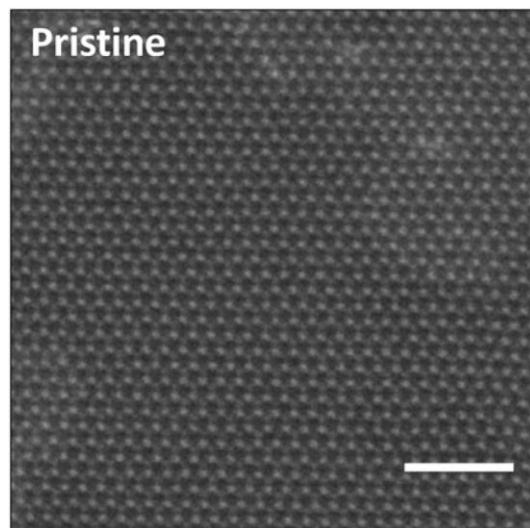
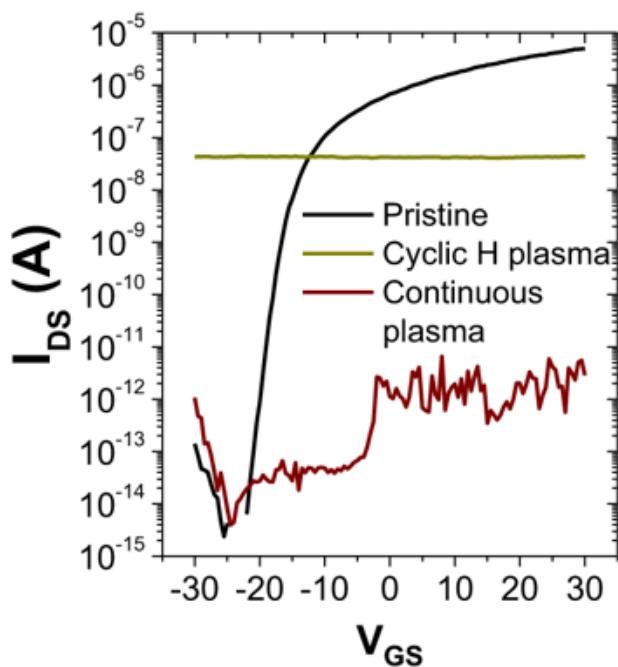
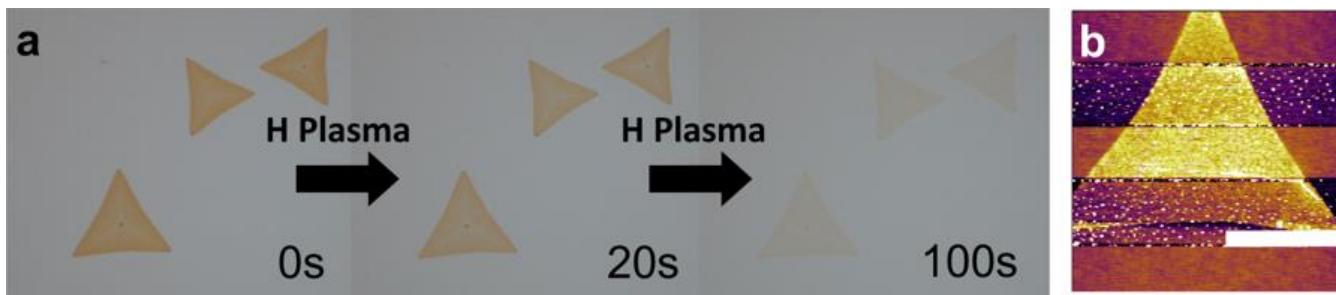


# Defect healing by chemical treatment: TFSI superacid

After:



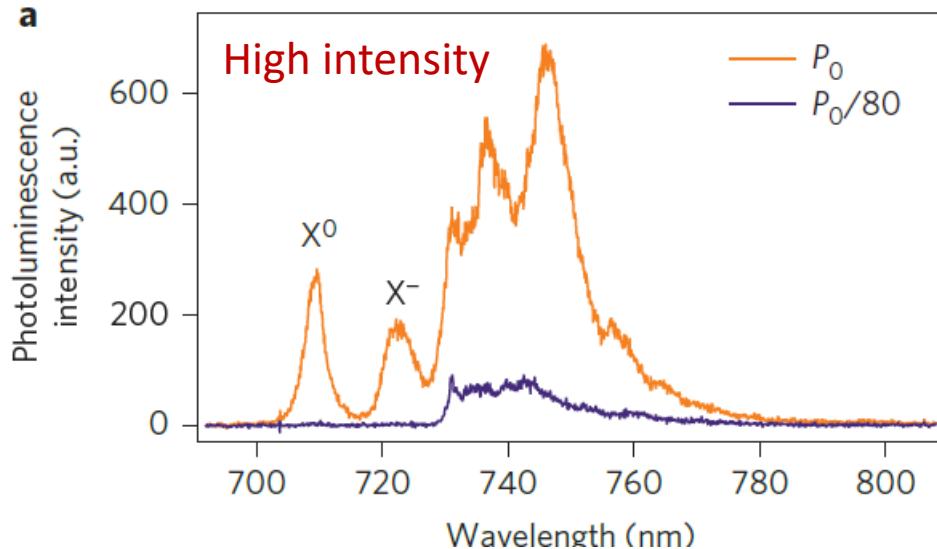
# Positive aspects: reduction of contact resistance



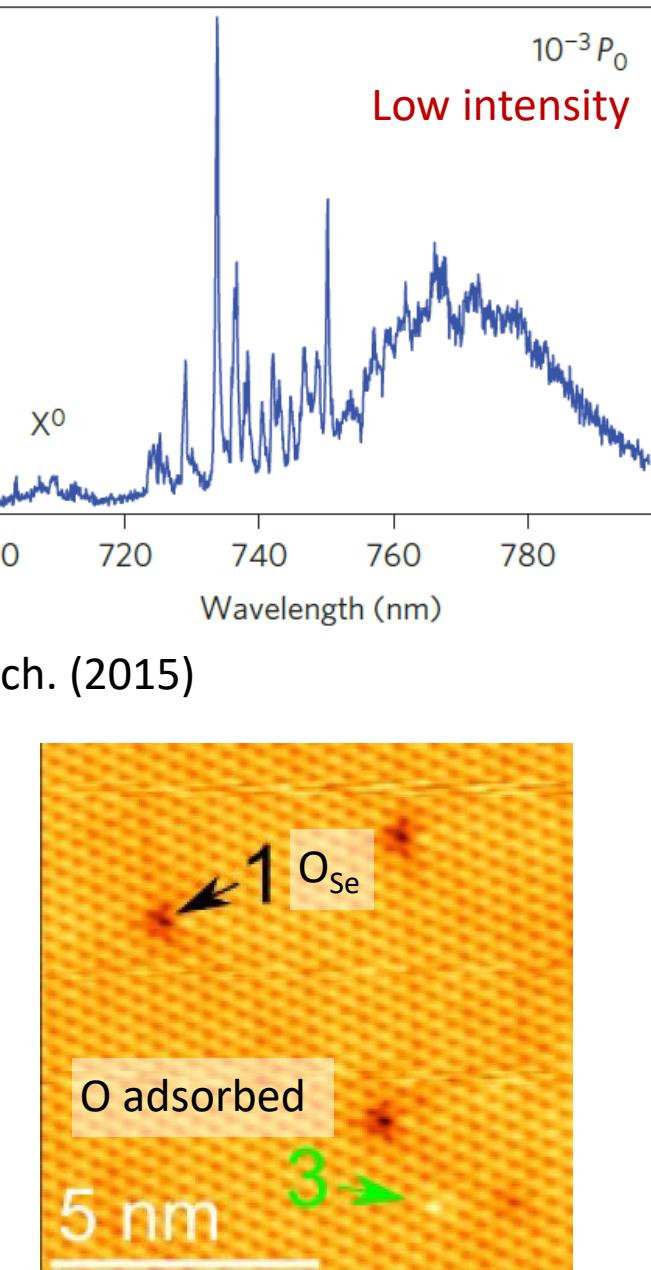
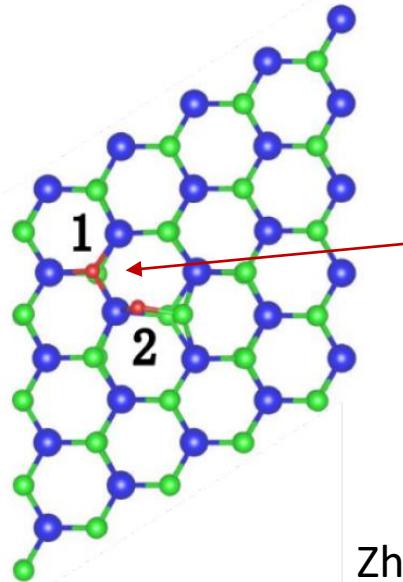
Stanford et al., npj 2D Materials and Applications (2019)

# Positive aspects: single-photon sources

Point defects in WSe<sub>2</sub> emit photons one by one

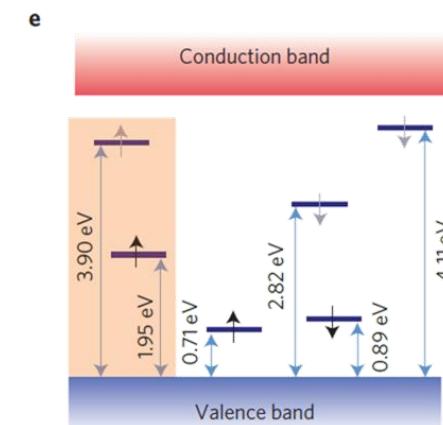
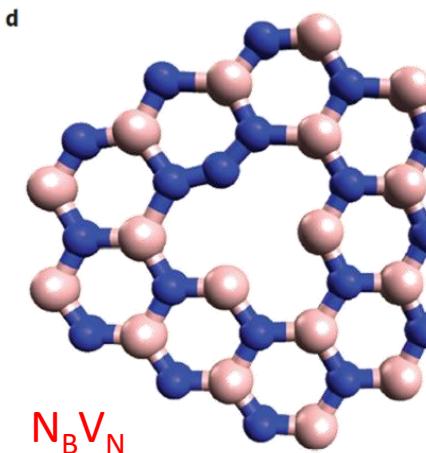
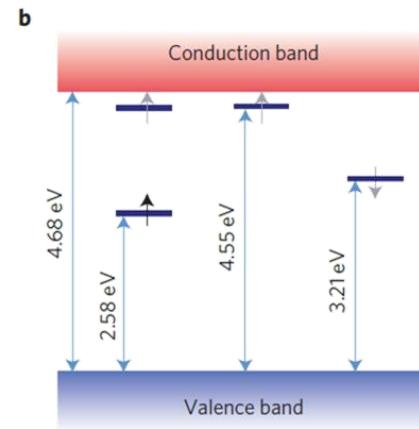
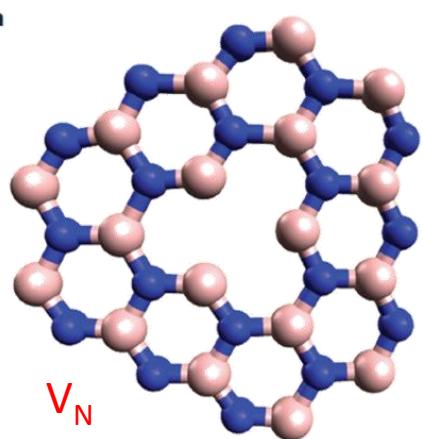
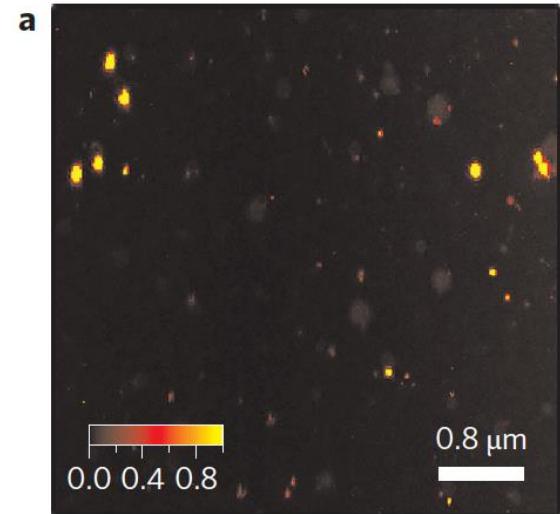
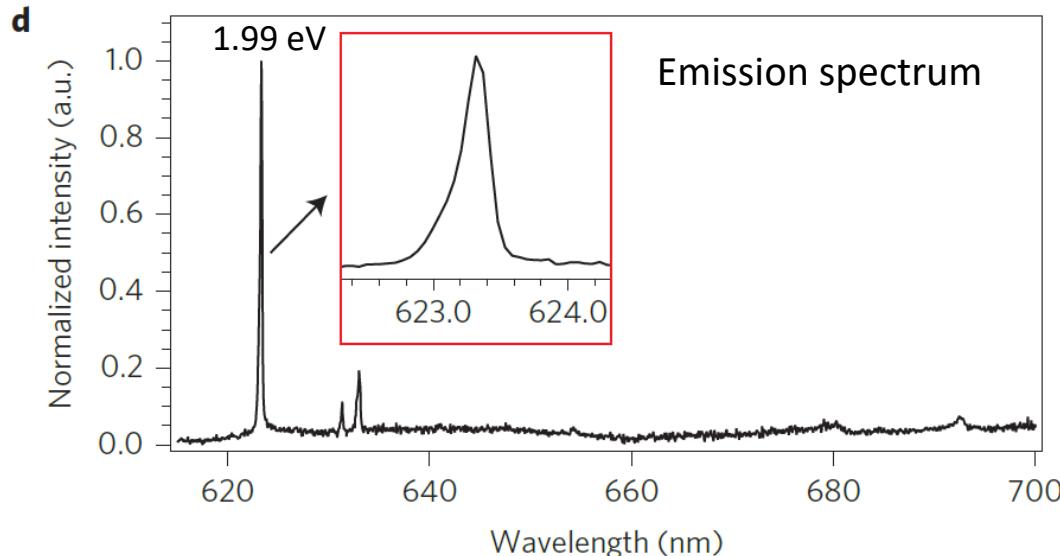


Srivastava et al., Nature Nanotech. (2015)

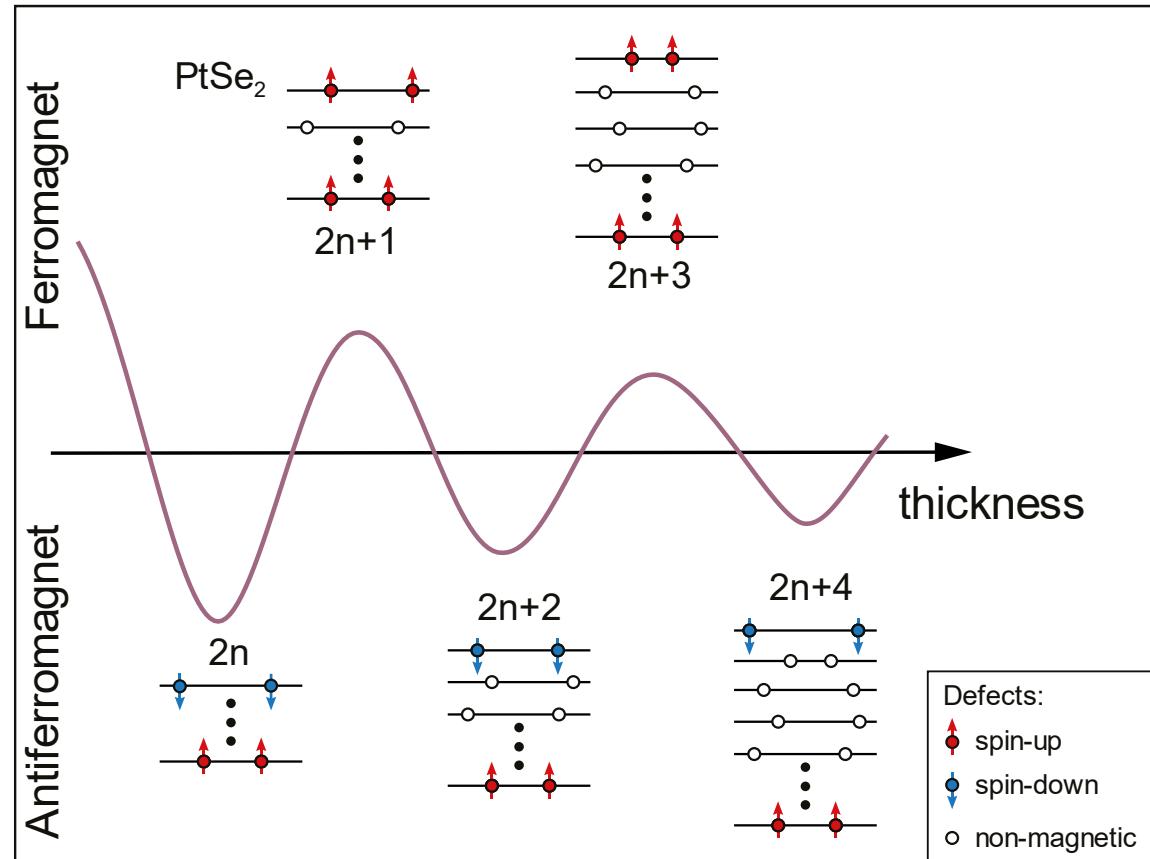
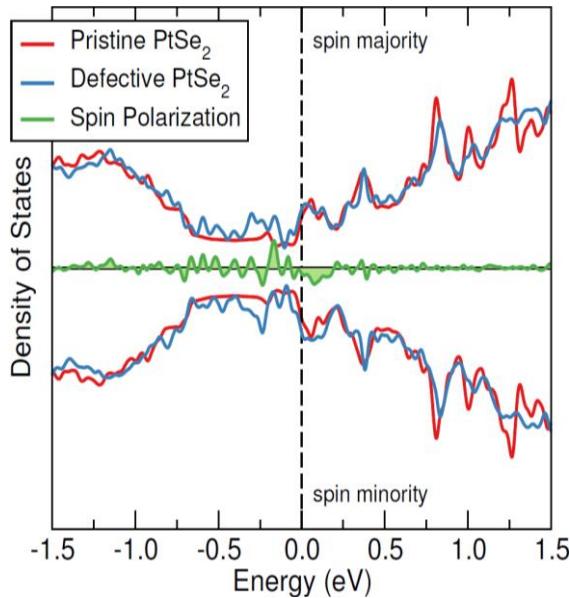
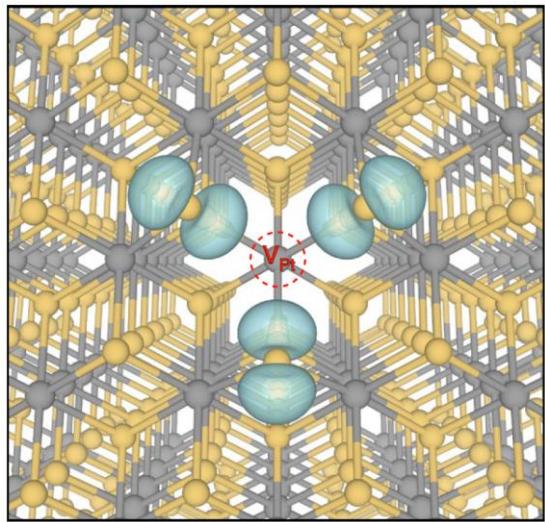


# Positive aspects: single-photon sources

Point defects in BN emit photons one by one



# Positive aspects: induced magnetism in $\text{PtSe}_2$



Avsar et al. Nature Nanotechnology (2019)

# Recapitulation

## Defect types

- Two-dimensional defects (wrinkles, ripples)
- Line defects
- Point defects

## Impact of point defects

- Reduced device performance due to disorder and charge trapping
- Quantifying their impact on electrical performance (transport and CV measurements)

## Point defect mitigation

- Dielectric environment
- Chemical treatment

## Positive applications of defects

- Doping, reduced contact resistance
- Single-photon sources
- Defect-induced magnetism